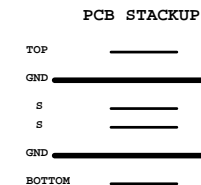


Project code: 91.4CG01.001  
PCB P/N : 48.4CG01.0SA  
REVISION : 08245-SA

JV50

ICH9M Functional Strap Definitions

ICH9 EDS 642879 Rev.1.5 page 92

Signal	Usage/When Sampled	Comment
HDA_SDOUT	XOR Chain Entrance/ PCIE Port Config1 bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low.When TP3 not pulled low at rising edge of PWROK,sets bit1 of RPC.PC(Config Registers: offset 224h). This signal has weak internal pull-down
HDA_SYNC	PCIE config1 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-down. Sets bit0 of RPC.PC(Config Registers:Offset 224h)
GNT2#/GPIO53	PCIE config2 bit2, Rising Edge of PWROK.	This signal has a weak internal pull-up. Sets bit2 of RPC.PC2(Config Registers:Offset 0224h)
GPIO20	Reserved	This signal should not be pulled high.
GNT1#/GPIO51	ESI Strap (Server Only) Rising Edge of PWROK	ESI compatible mode is for server platforms only. This signal should not be pulled low for desttop and mobile.
GNT3#/GPIO55	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT0#:SPI_CS1#/GPIO58	Boot BIOS Destination Selection 0:1. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT0# is MSB, 01-SPI, 10-PCI, 11-LPC.
SPI_MOSI	Integrated TPM Enable, Rising Edge of CLPWROK	Sample low: the Integrated TPM will be disabled. Sample high: the MCH TPM enable strap is sampled low and the TPM Disable bit is clear, the Integrated TPM will be enable.
GPIO49	DMI Termination Voltage. Rising Edge of PWROK.	The signal is required to be low for desktop applications and required to be high for mobile applications.
SATALED#	PCI Express Lane Reversal. Rising Edge of PWROK.	Signal has weak internal pull-up. Sets bit 27 of MPC.LR(Device 28:Function 0:Offset D8)
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH9 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.
GPIO33/HDA_DOCK_EN#	Flash Descriptor Security Override Strap Rising Edge of PWROK	Sampled low:the Flash Descriptor Security will be overridden. If high,the security measures will be in effect.This should only be enabled in manufacturing environments using an external pull-up resistor.

ICH9M Integrated Pull-up and Pull-down Resistors

ICH9 EDS 642879 Rev.1.5

SIGNAL	Resistor Type/Value
CL_CLK[1:0]	PULL-UP 20K
CL_DATA[1:0]	PULL-UP 20K
CL_RST0#	PULL-UP 20K
DPRS LPVR/GPIO16	PULL-DOWN 20K
ENERGY_DETECT	PULL-UP 20K
HDA_BIT_CLK	PULL-DOWN 20K
HDA_DOCK_EN#/GPIO33	PULL-UP 20K
HDA_RST#	PULL-DOWN 20K
HDA_SDIN[3:0]	PULL-DOWN 20K
HDA_SDOUT	PULL-DOWN 20K
HDA_SYNC	PULL-DOWN 20K
GLAN_DOCK#	The pull-up or pull-down active when configured for native GLAN DOCK# functionality and determined by LAN controller
GNT[3:0]#/GPIO[55,53,51]	PULL-UP 20K
GPIO[20]	PULL-DOWN 20K
GPIO[49]	PULL-UP 20K
LDA[3:0]#/FWH[3:0]#	PULL-UP 20K
LAN_RXD[2:0]	PULL-UP 20K
LDRQ[0]	PULL-UP 20K
LDRQ[1]/GPIO23	PULL-UP 20K
PME#	PULL-UP 20K
PWRBTN#	PULL-UP 20K
SATALED#	PULL-UP 15K
SPI_CS1#/GPIO58/CLGPIO6	PULL-UP 20K
SPI_MOSI	PULL-DOWN 20K
SPI_MISO	PULL-UP 20K
SPKR	PULL-DOWN 20K
TACH_[3:0]	PULL-UP 20K
TP[3]	PULL-UP 20K
USB[11:0][P,N]	PULL-DOWN 15K

Cantiga chipset and ICH9M I/O controller Hub strapping configuration

Montevina Platform Design guide 22339 0.5 page 218

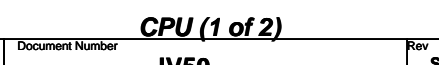
Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	000 = FSB1067 011 = FSB667 010 = FSB800 others = Reserved
CFG[4:3] CFG8 CFG[15:14] CFG[18:17]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (Default)
CFG6	iTPM Host Interface	0= The iTPM Host Interface is enabled(Note2) 1=The iTPM Host Interface is disalbed(default)
CFG7	Intel Management engine Crypto strap	0 = Transport Layer Security (TLS) cipher suite with no confidentiality 1 = TLS cipher suite with confidentiality (default)
CFG9	PCIE Graphics Lane	0 = Reverse Lanes,15->0,14->1 ect.. 1= Normal operation(Default):Lane Numbered in order
CFG10	PCIE Loopback enable	0 = Enable (Note 3) 1= Disabled (default)
CFG[13:12]	XOR/ALL	00 = Reserve 10 = XOR mode Enabled 01 = ALLZ mode Enabled (Note 3) 11 = Disabled (default)
CFG16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG19	DMI Lane Reversal	0 = Normal operation(Default): Lane Numbered in Order 1 = Reverse Lanes DMI x4 mode[MCH -> ICH]:(3->0,2->1,1->2and0->3 DMI x2 mode[MCH -> ICH]:(3->0,2->1)
CFG20	Digital Display Port (SDVO/DP/iHDMI) Concurrent with PCIE	0 = Only Digital Display Port or PCIE is operational (Default) 1 = Digital display Port and PCIE are operating simulataneously via the PEG port
SDVO_CTRLDATA	SDVO Present	0 =No SDVO Card Present (Default) 1 = SDVO Card Present
L_DDC_DATA	Local Flat Panel (LFP) Present	0 = LFP Disabled (Default) 1= LFP Card Present; PCIE disabled

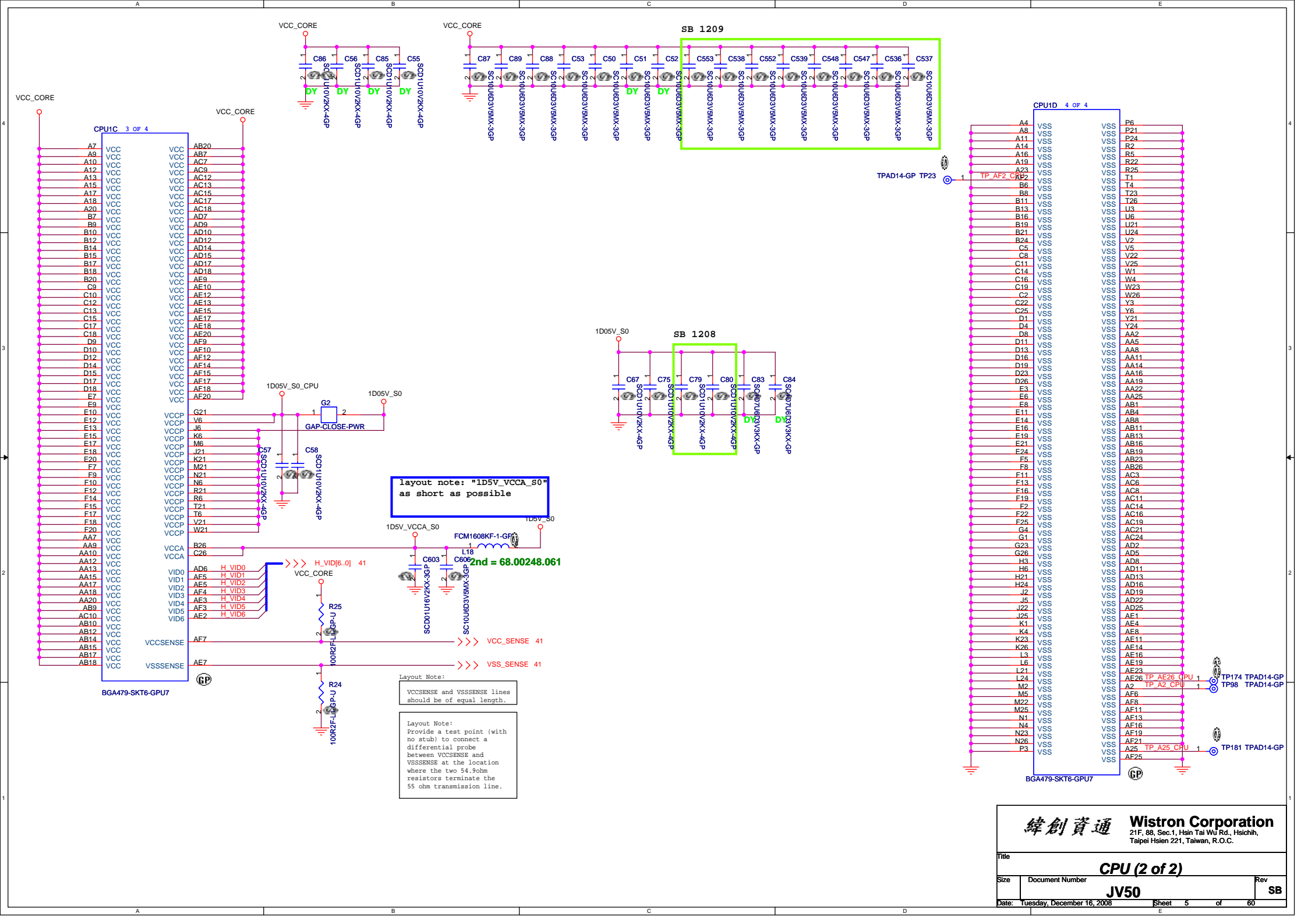
NOTE:  
1. All strap signals are sampled with respect to the leading edge of the (G)MCH Power OK (PWROK) signal.  
2. iTPM can be disabled by a 'Soft-Strap' option in the Flash-decriptor section of the Firmware. This 'Soft-Strap' is activated only after enabling iTPM via CFG6.  
Only one of the CFG10/CFG12/CFG13 straps can be enabled at any time.

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
Reference			
Size A3	Document Number	Rev	SB
JV50			
Date: Tuesday, December 16, 2008			
Sheet 2		of 60	

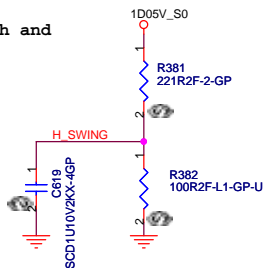






H\_SWING routing Trace width and Spacing use 10 / 20 mil

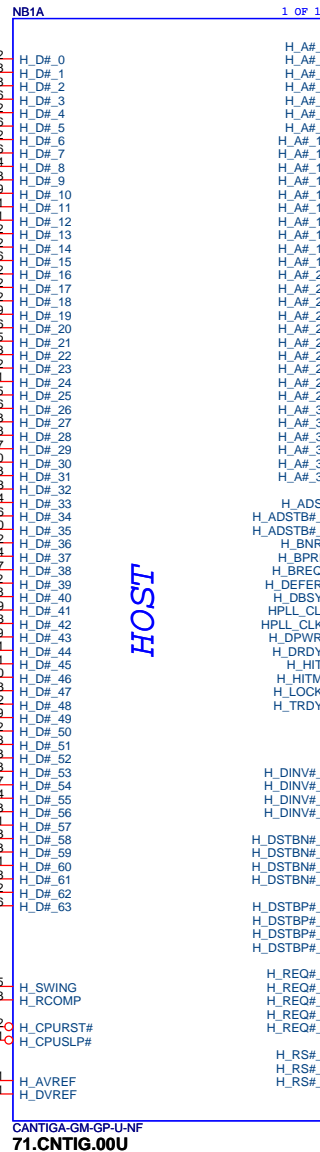
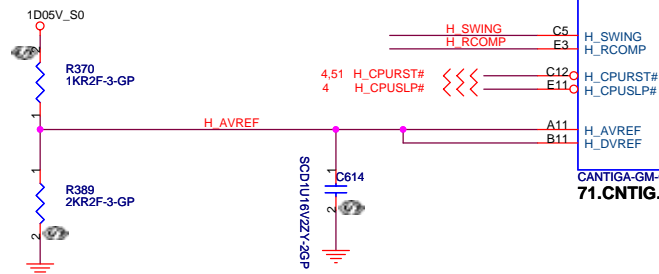
H\_SWING Resistors and Capacitors close MCH  
500 mil ( MAX )



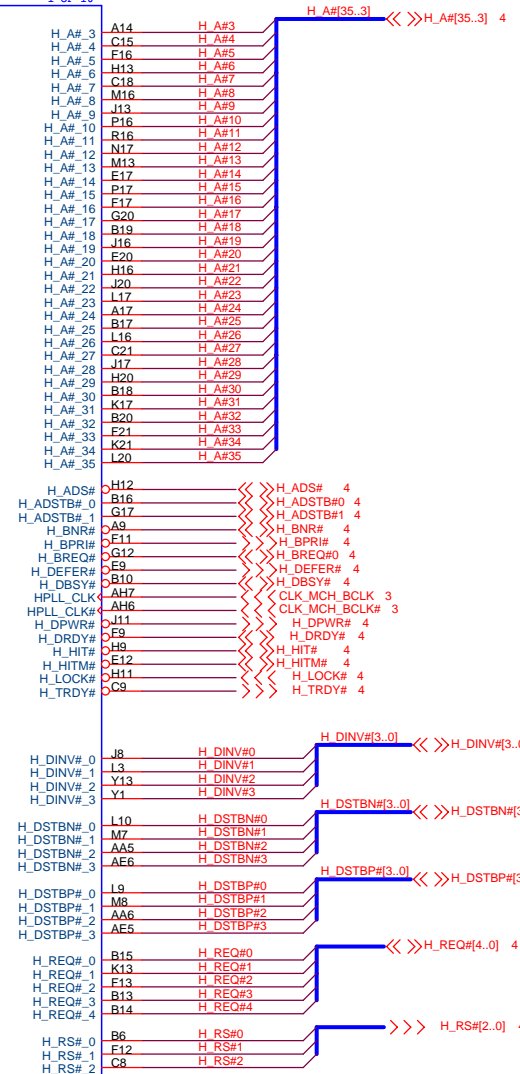
H\_RCOMP routing Trace width and Spacing use 10 / 20 mil



Place them near to the chip ( < 0.5")



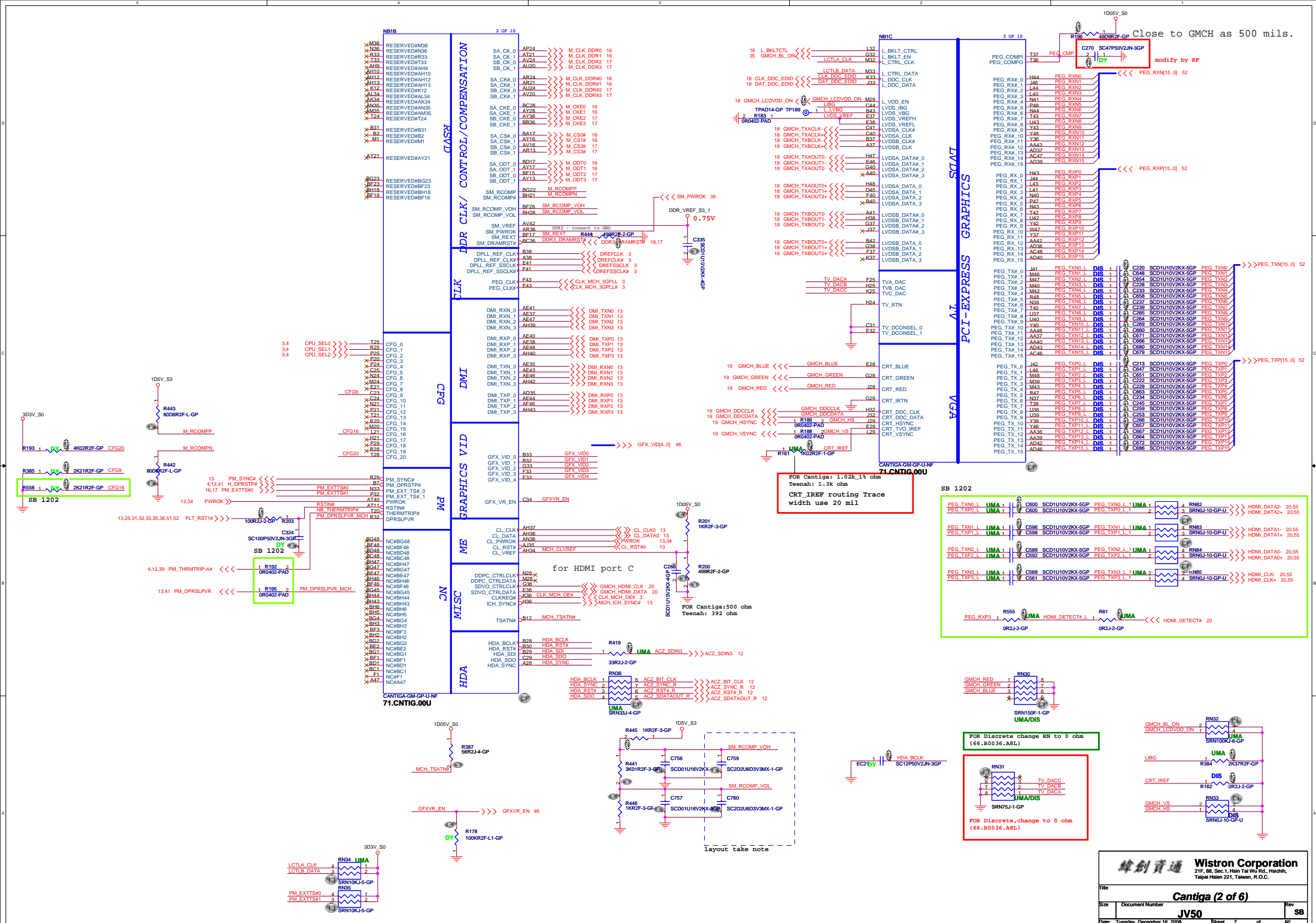
ISOH

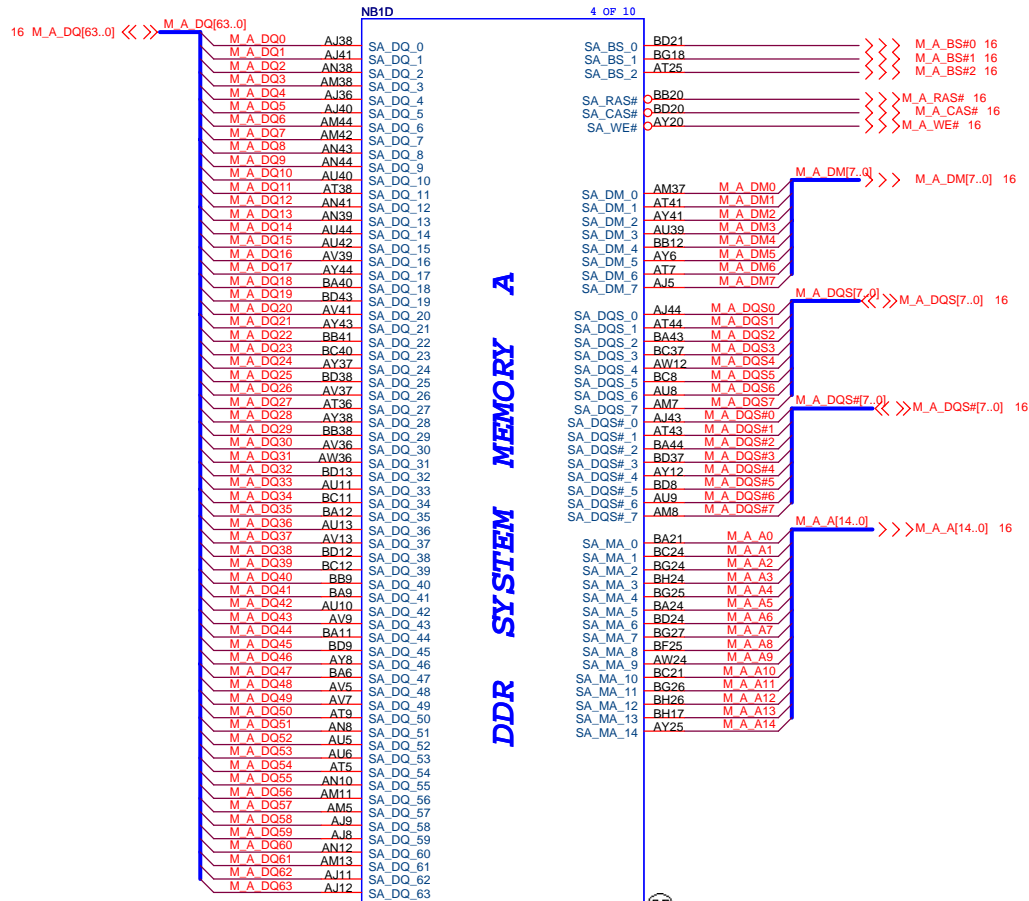


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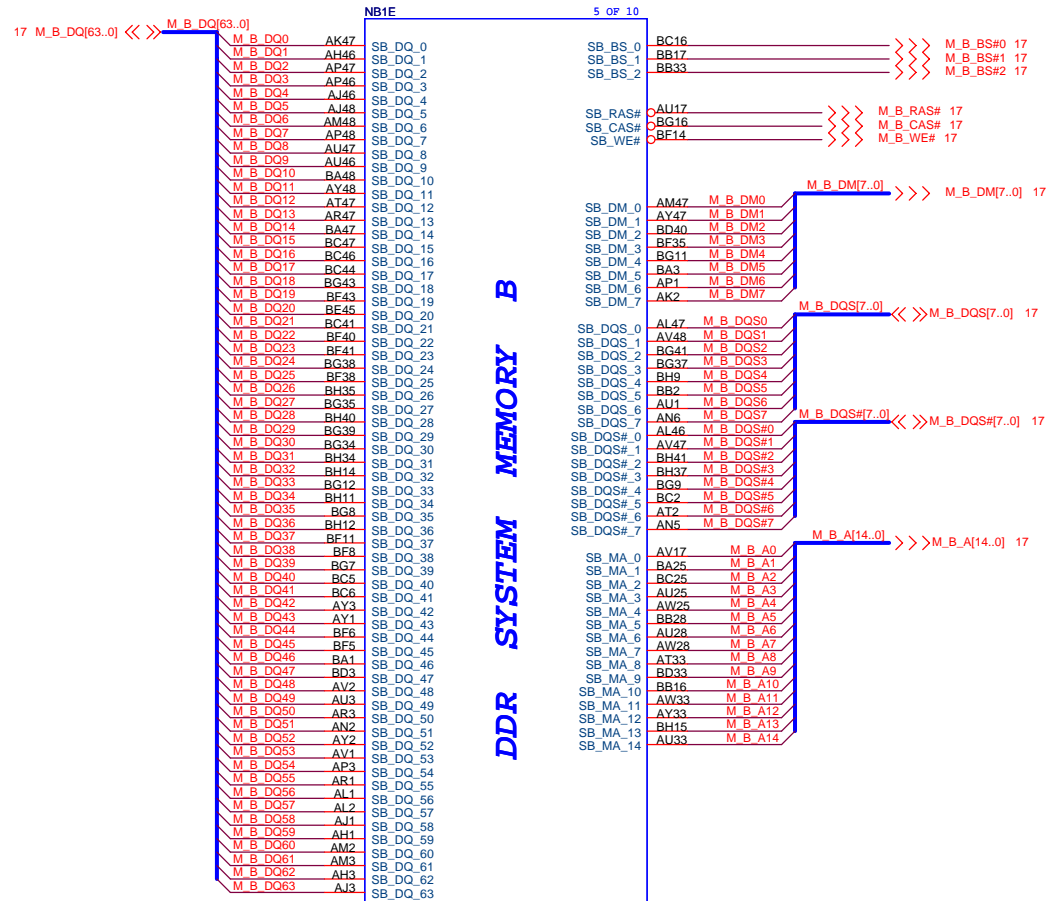
緯創資通 Wistron Corporation  
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Taipei Hsien 221, Taiwan, R.O.C.







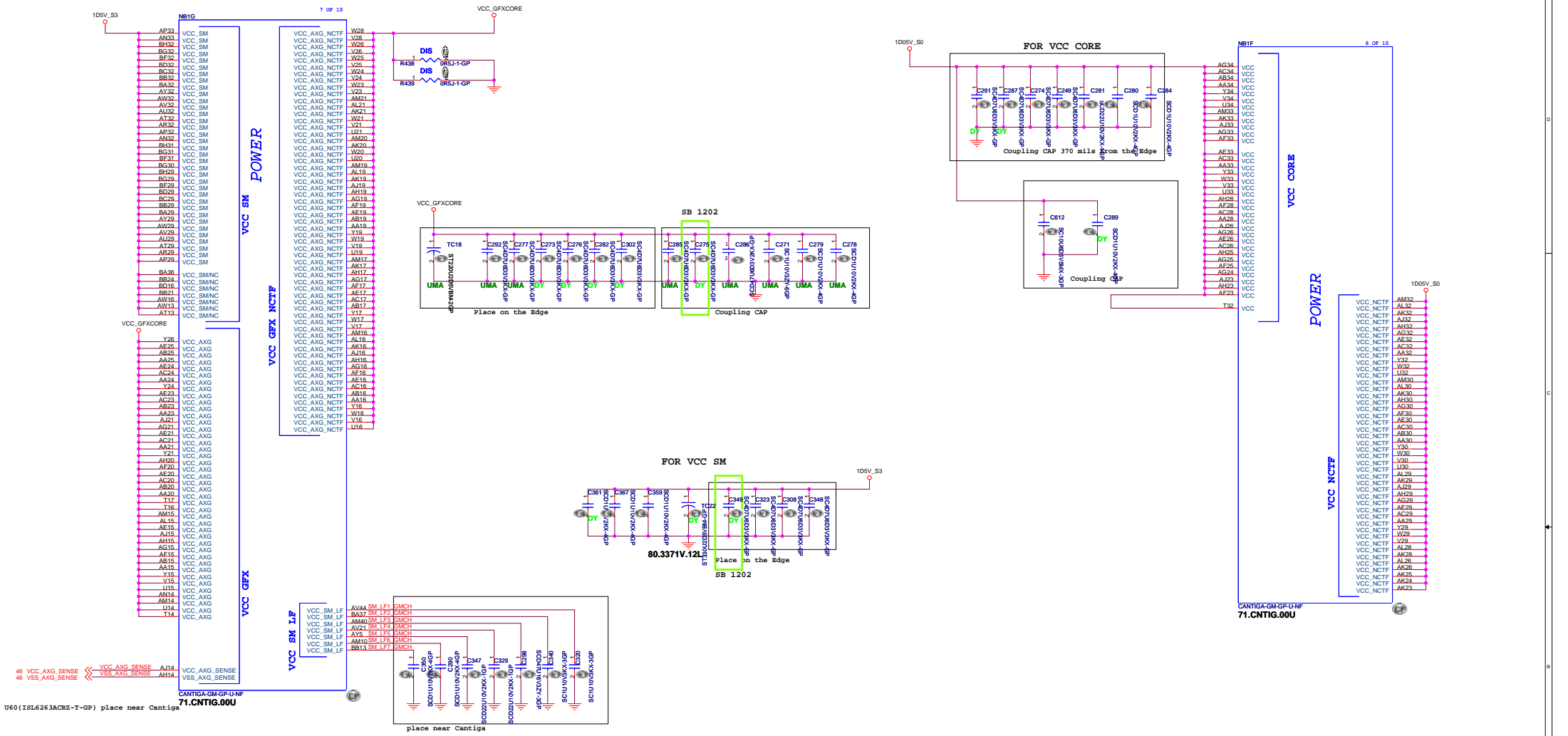
CANTIGA-GM-GP-U-NF  
71.CNTIG.00U



CANTIGA-GM-GP-U-NF  
71.CNTIG.00U

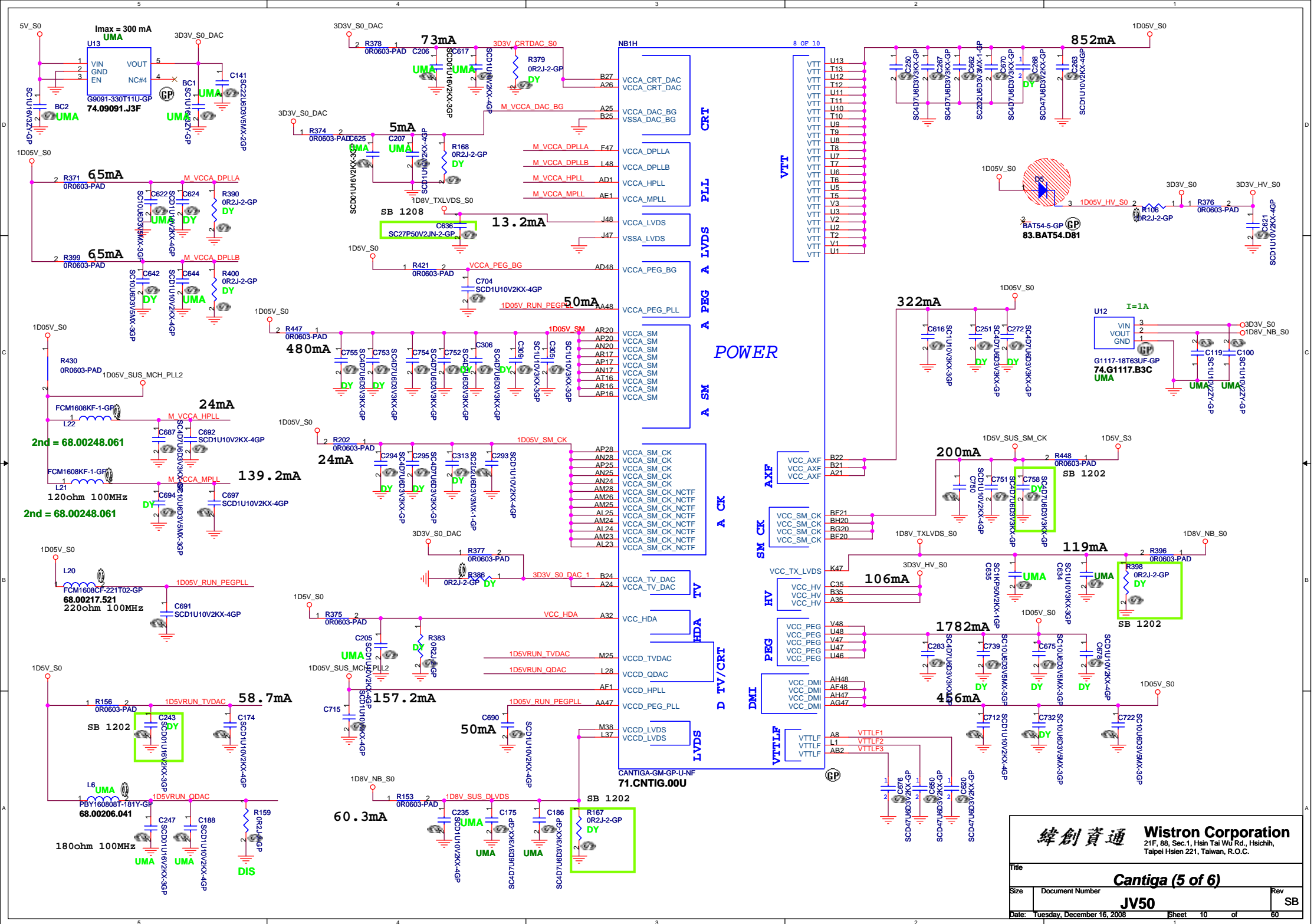
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Taipei Hsien 221, Taiwan, R.O.C.

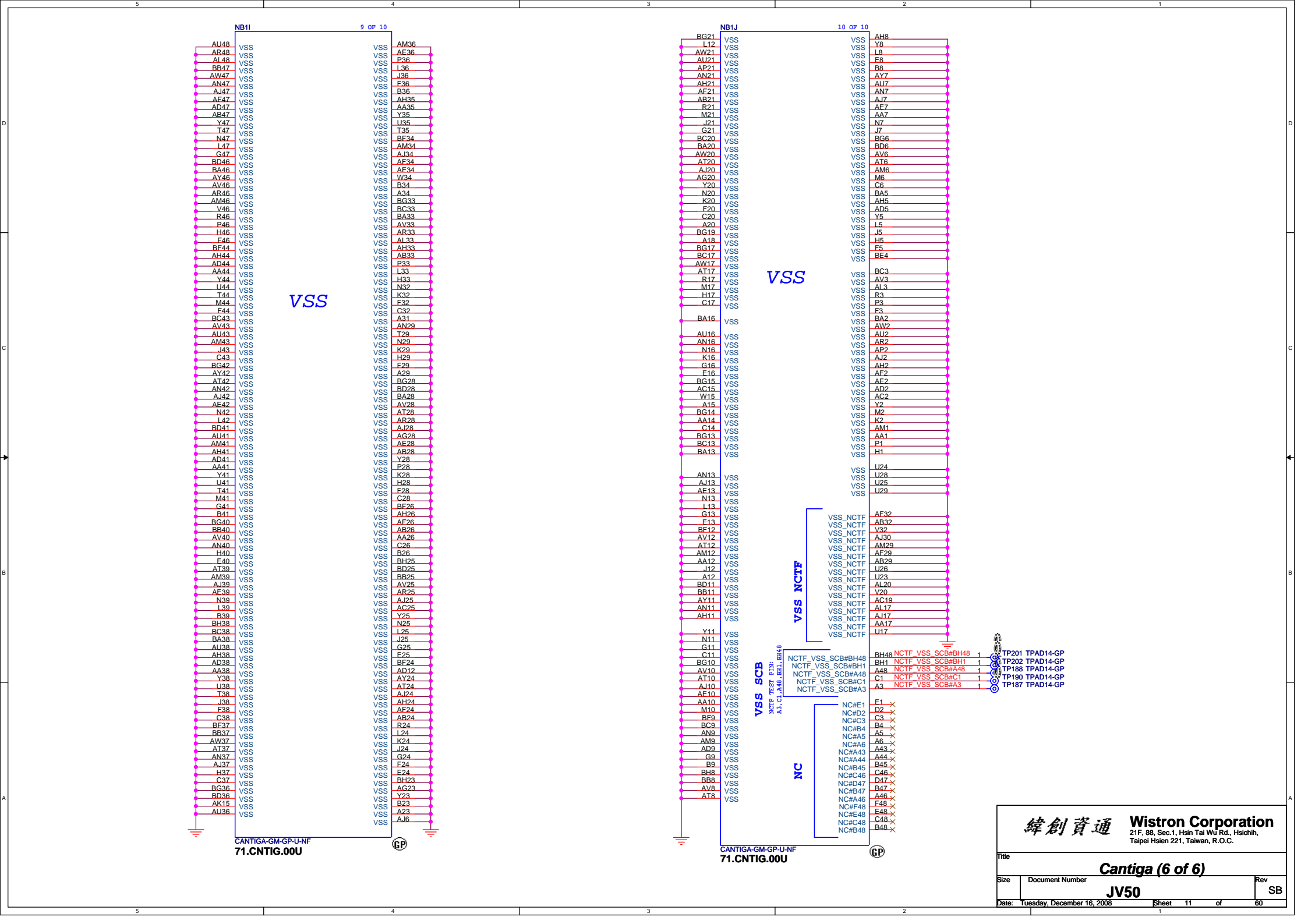
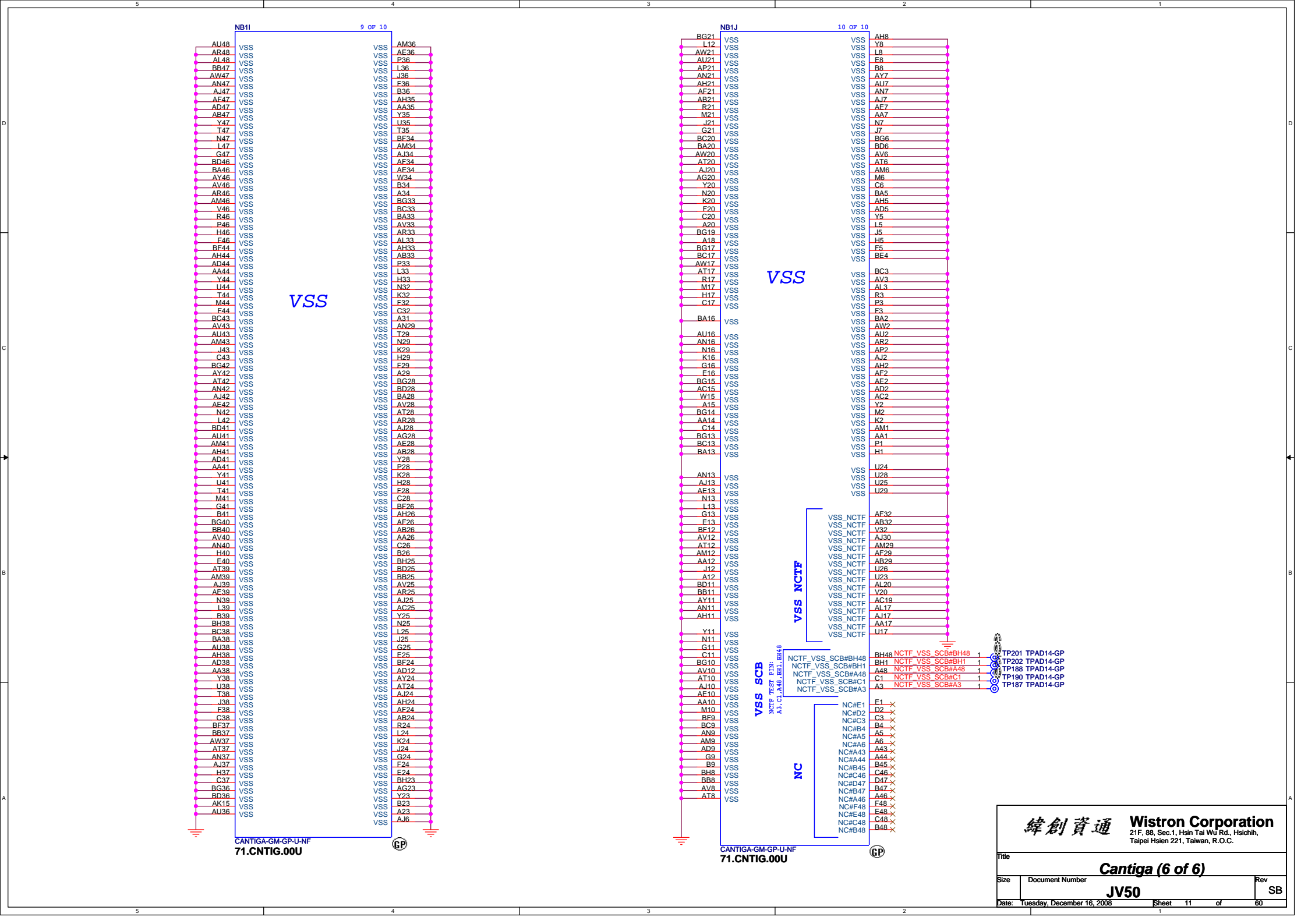


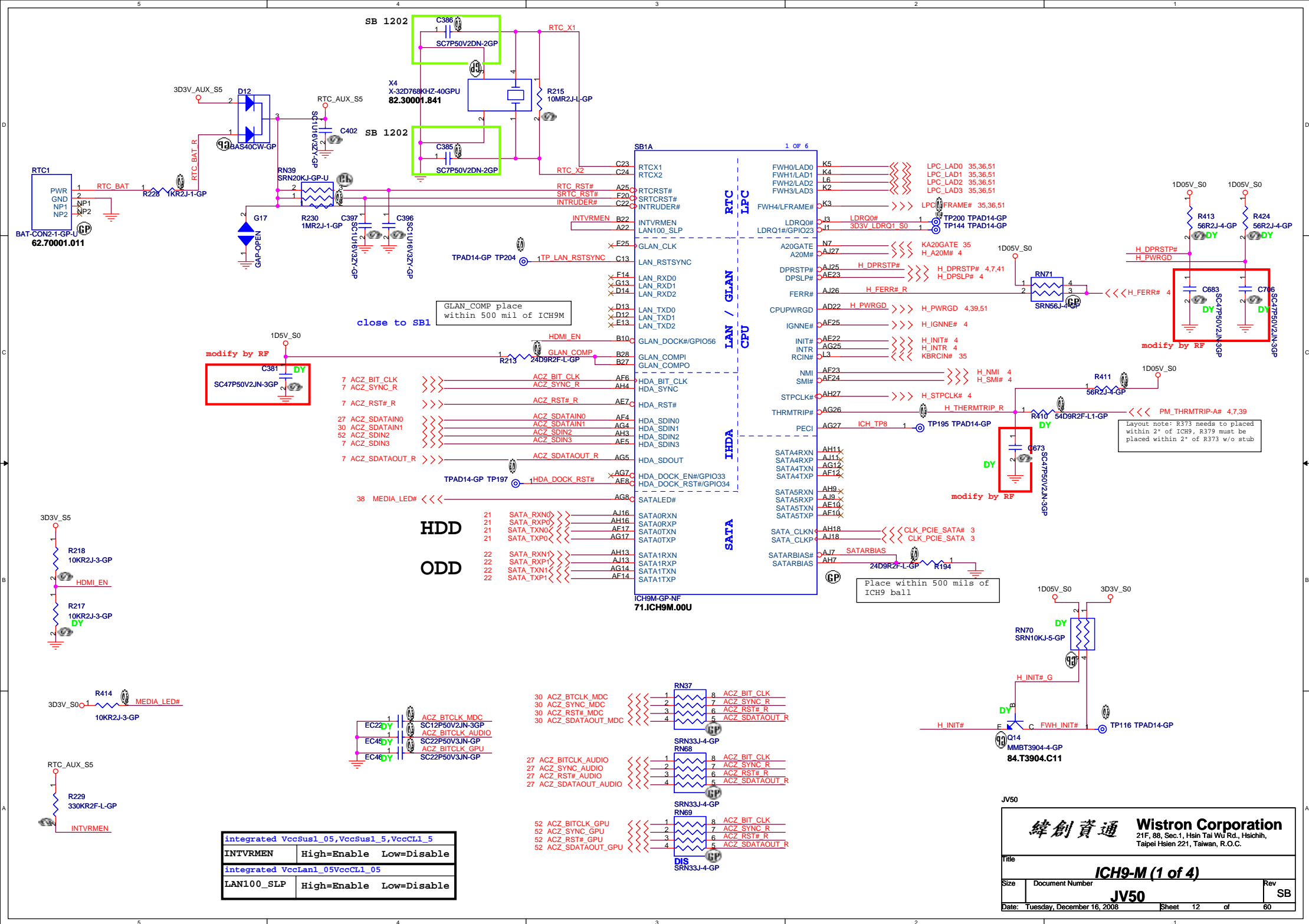


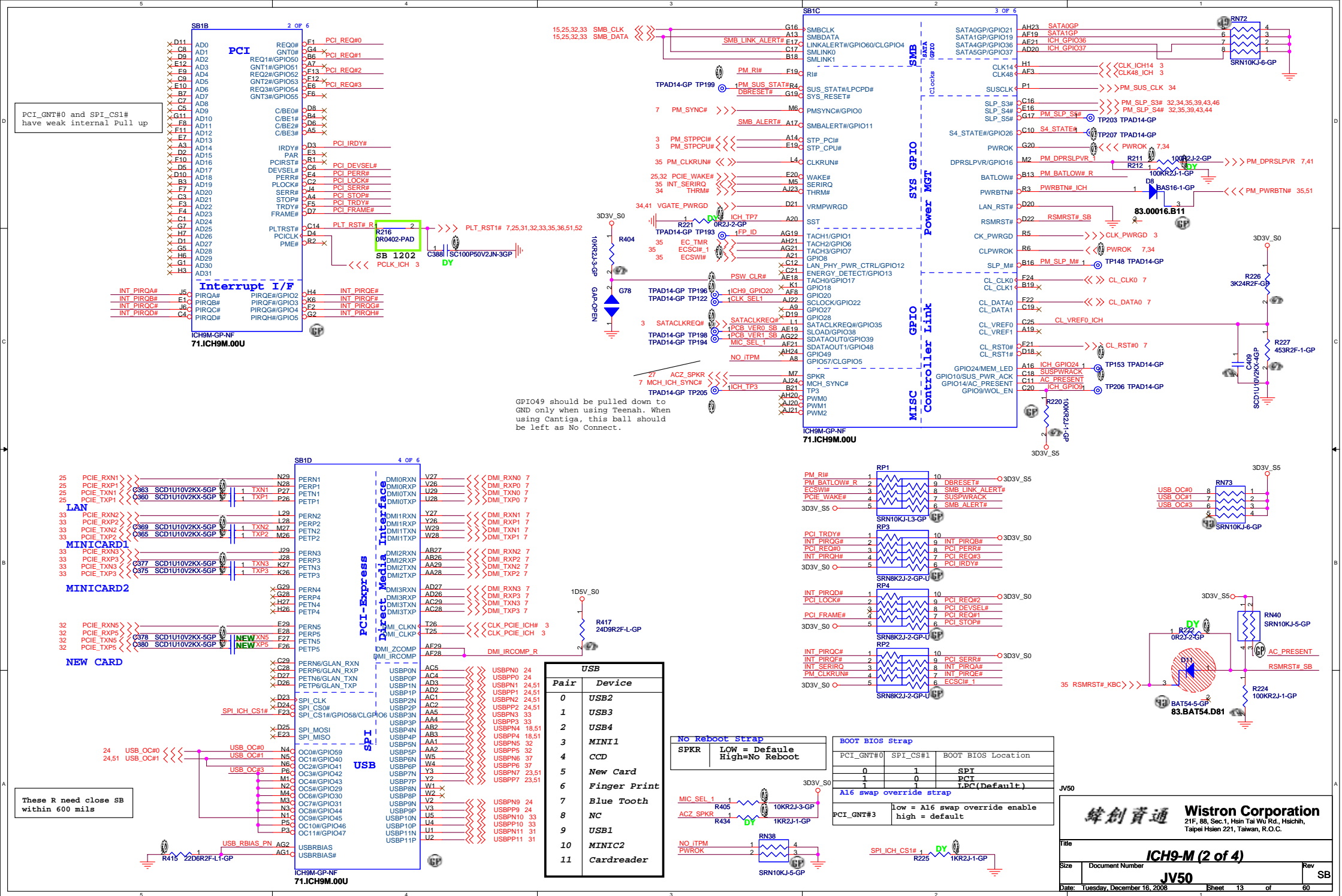
46 VCC\_AXG\_SENSE << VCC\_AXG\_SENSE\_A114  
46 VSS\_AXG\_SENSE << VSS\_AXG\_SENSE\_AH14  
VCC\_AXG\_SENSE  
VSS\_AXG\_SENSE  
CANTIGA-GM-GP-U-NF  
71.CNTIG.00U

U60 (ISL6263ACRZ-T-GP) place near Cantiga

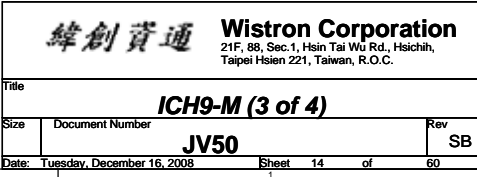








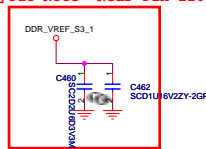




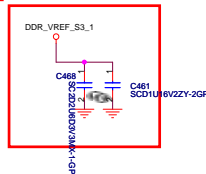





M A D032	129	0032
M A D033	131	0033
M A D034	141	0034
M A D035	143	0035
M A D036	130	0036
M A D037	132	0037
M A D038	140	0038
M A D039	142	0039
M A D040	147	0040
M A D041	149	0041
M A D042	158	0042
M A D043	167	0043
M A D044	168	0044
M A D045	148	0045
M A D046	158	0046
M A D047	160	0047
M A D048	163	0048
M A D049	165	0049
M A D050	175	0050
M A D051	177	0051
M A D052	164	0052
M A D053	166	0053
M A D054	174	0054
M A D055	176	0055
M A D056	181	0056
M A D057	183	0057
M A D058	181	0058
M A D059	193	0059
M A D060	180	0060
M A D061	182	0061
M A D062	192	0062
M A D063	194	0063

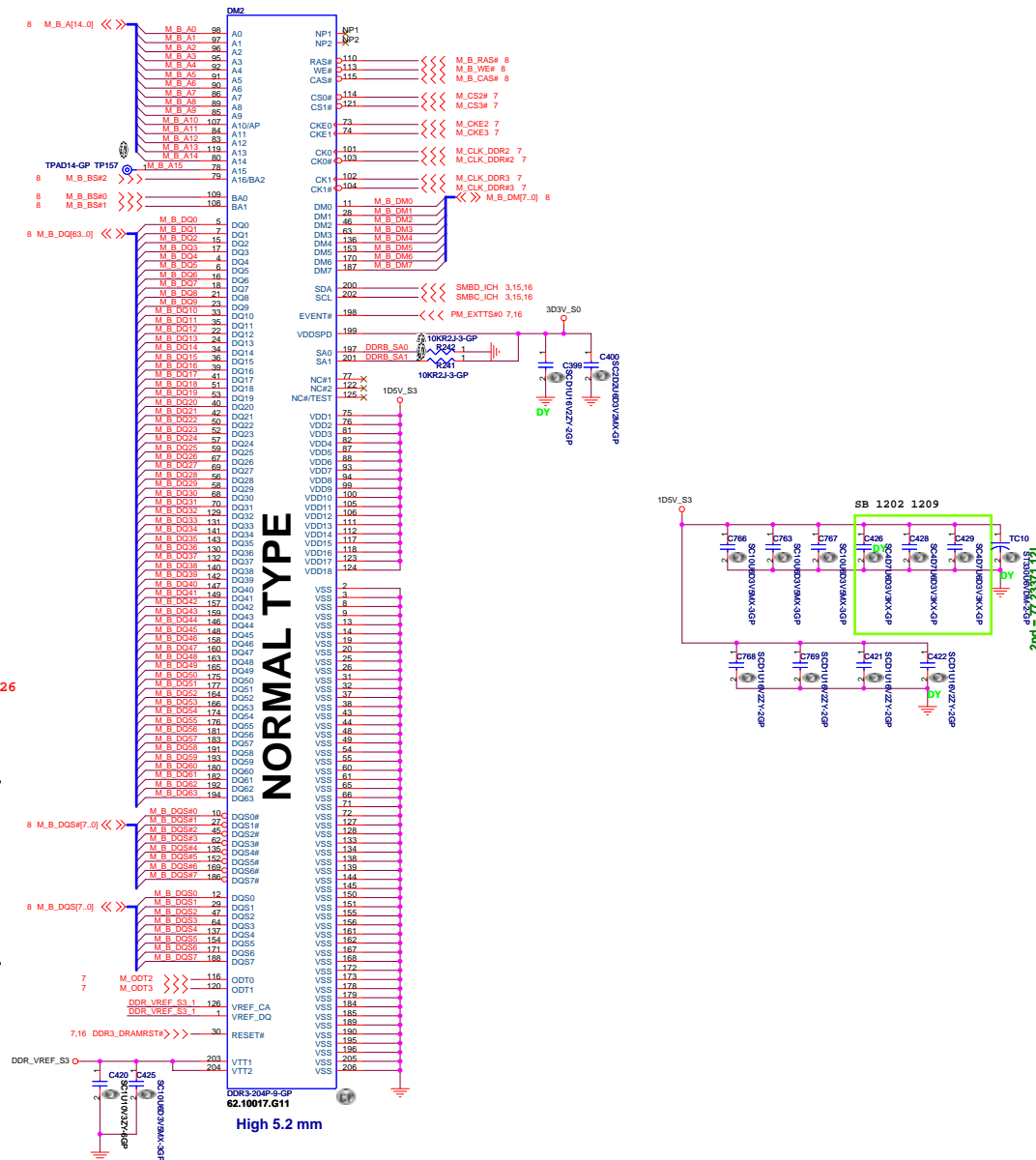


Layout Note : Near Pin 1

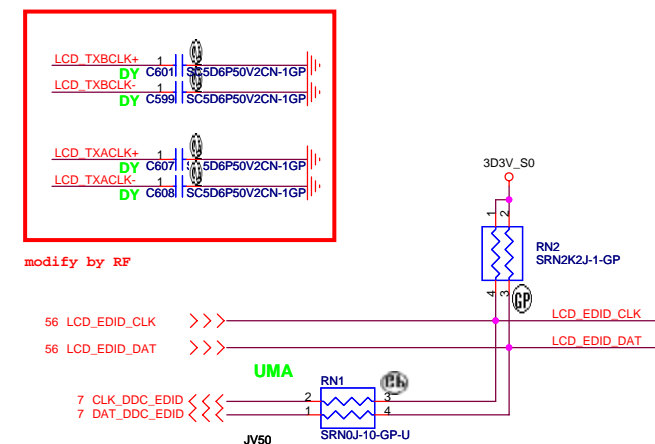
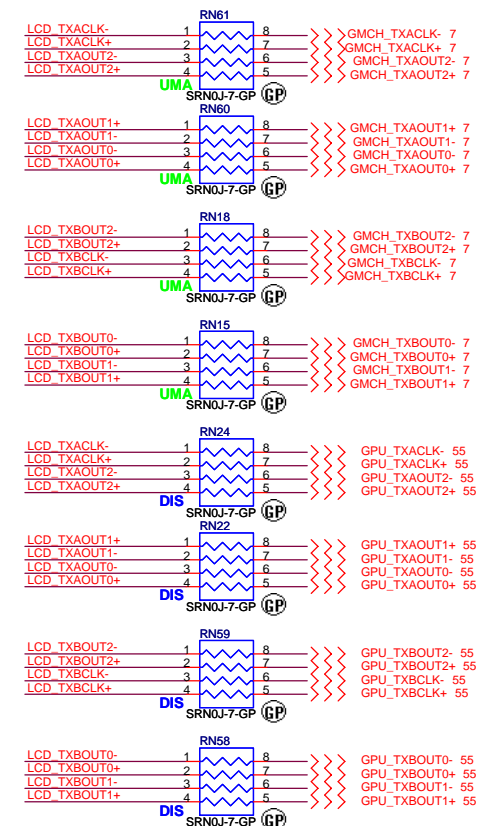
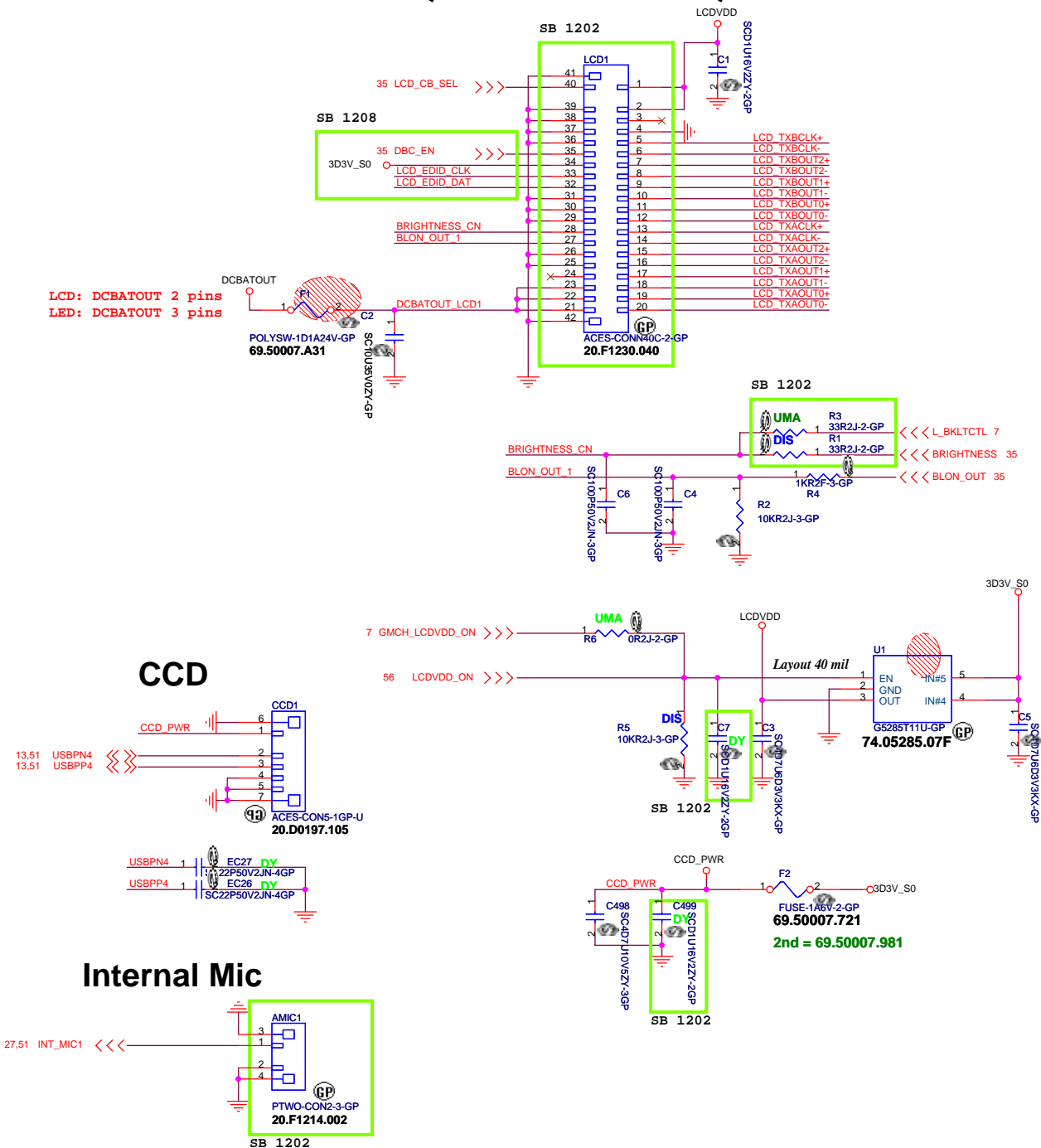


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Title		
<b>DDR3 Socket</b>		
Size	Document Number	Rev
	<b>JV50</b>	<b>SB</b>
Date:	Tuesday, December 16, 2008	Sheet 16 of 60

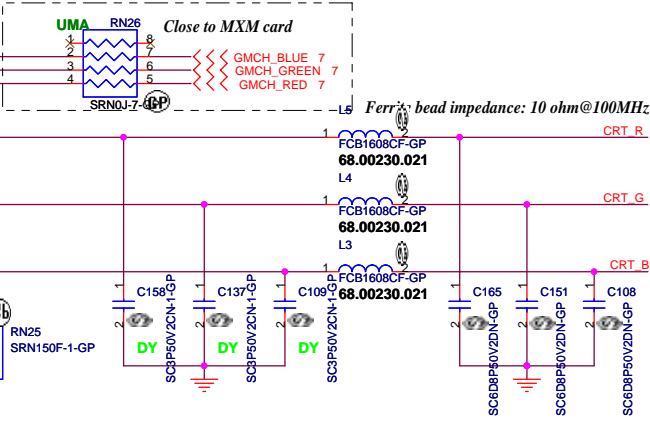
# DDR3 SOCKET\_2



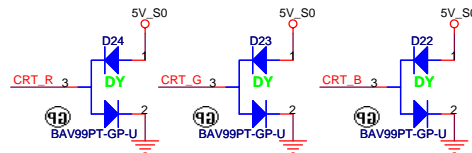
## LCD/INVERTER/CCD CONN



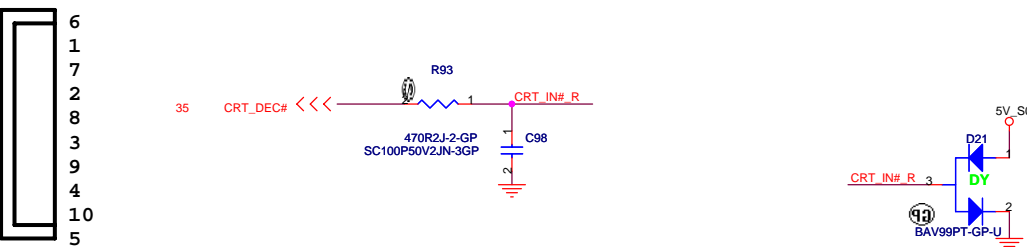
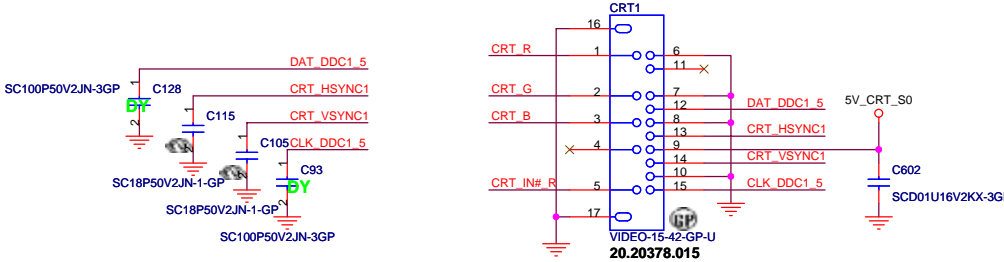
Layout Note:  
Place these resistors  
close to the CRT-out  
connector



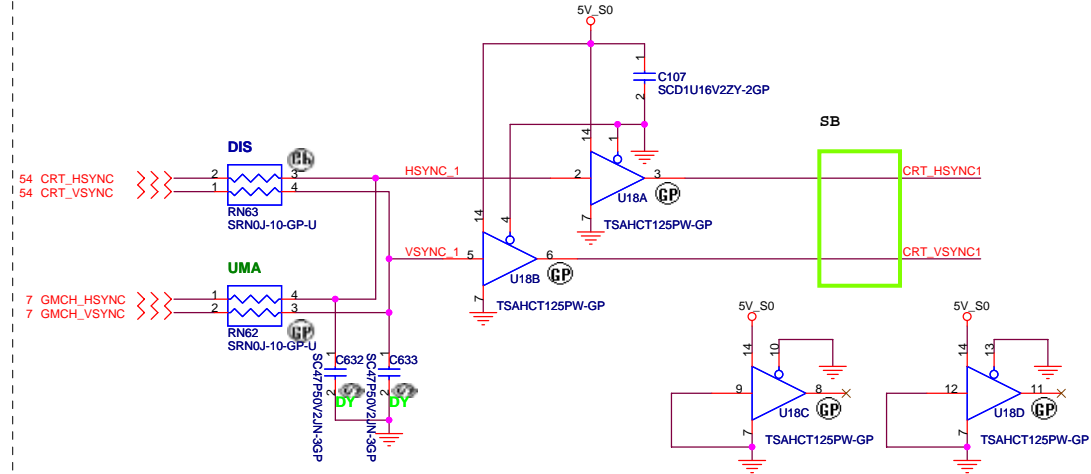
**Layout Note:**  
\* Must be a ground return path between this ground and the ground on the VGA connector.  
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.



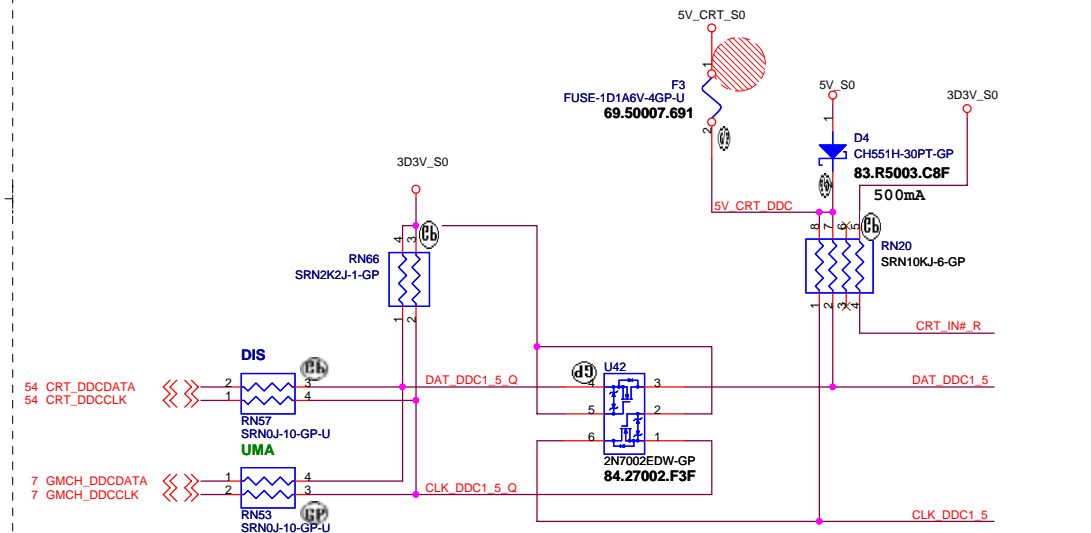
## CRT I/F & CONNECTOR

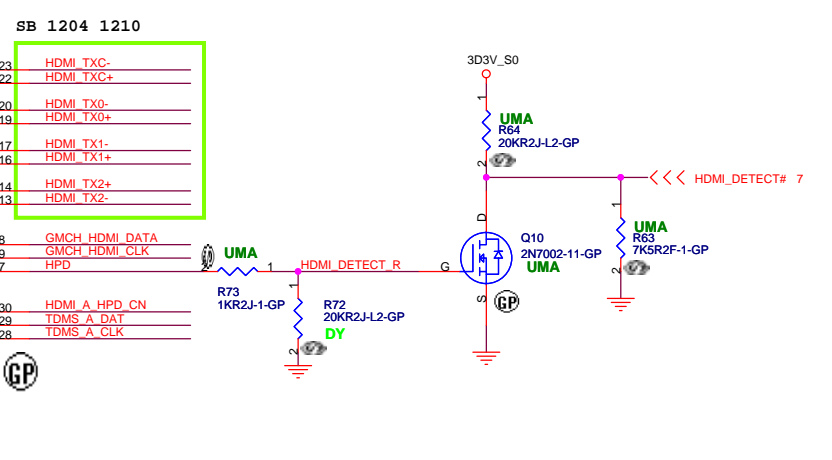
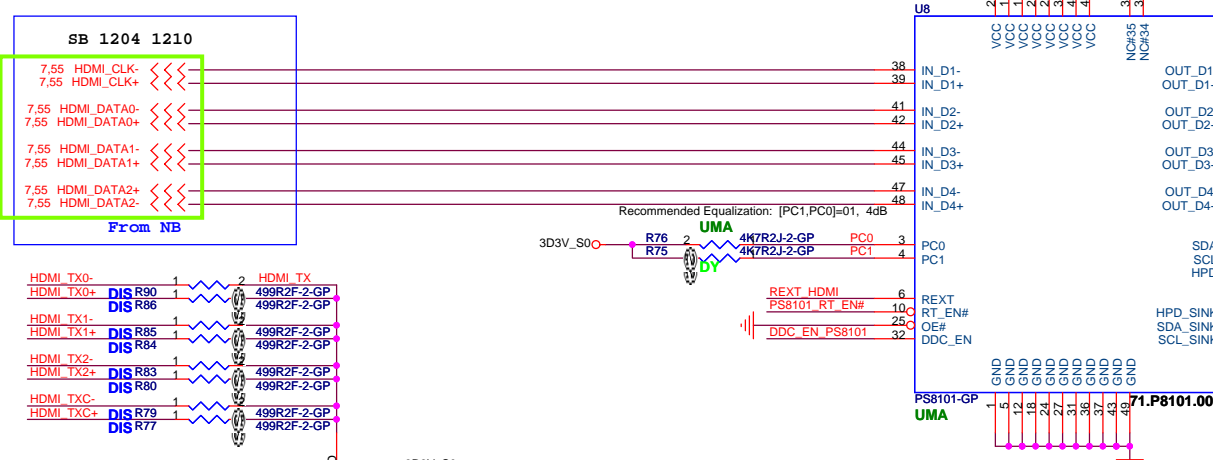
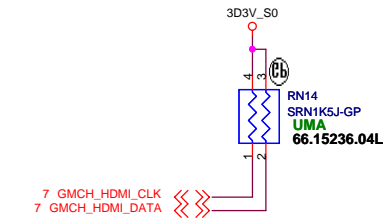
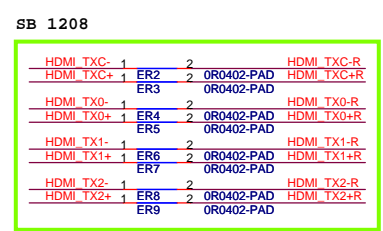
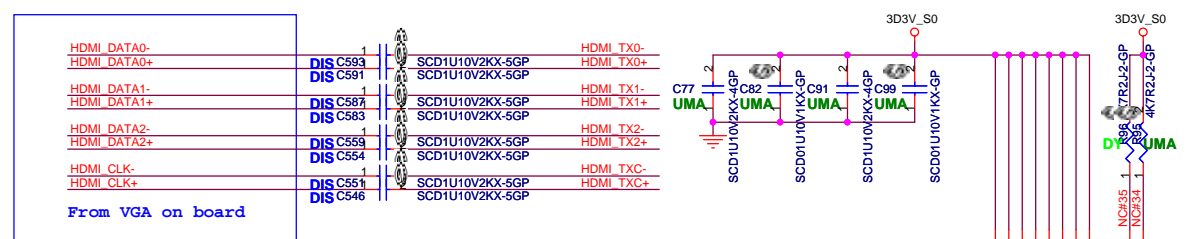
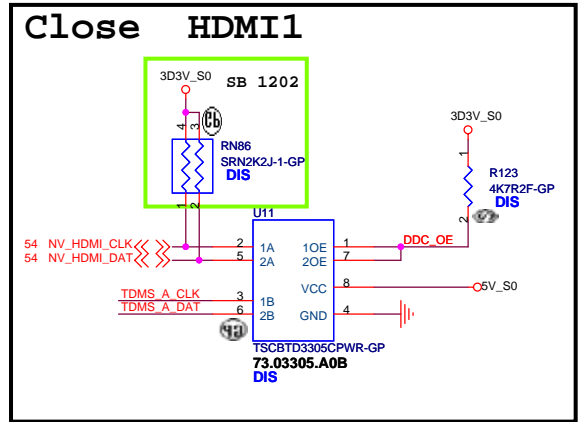
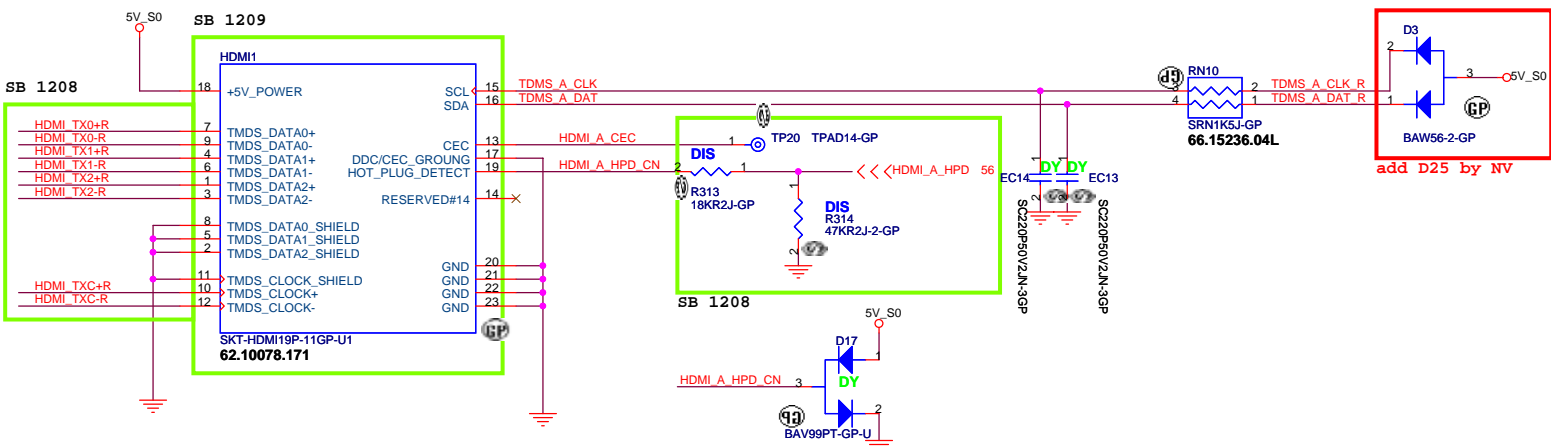


## Hsync & Vsync level shift



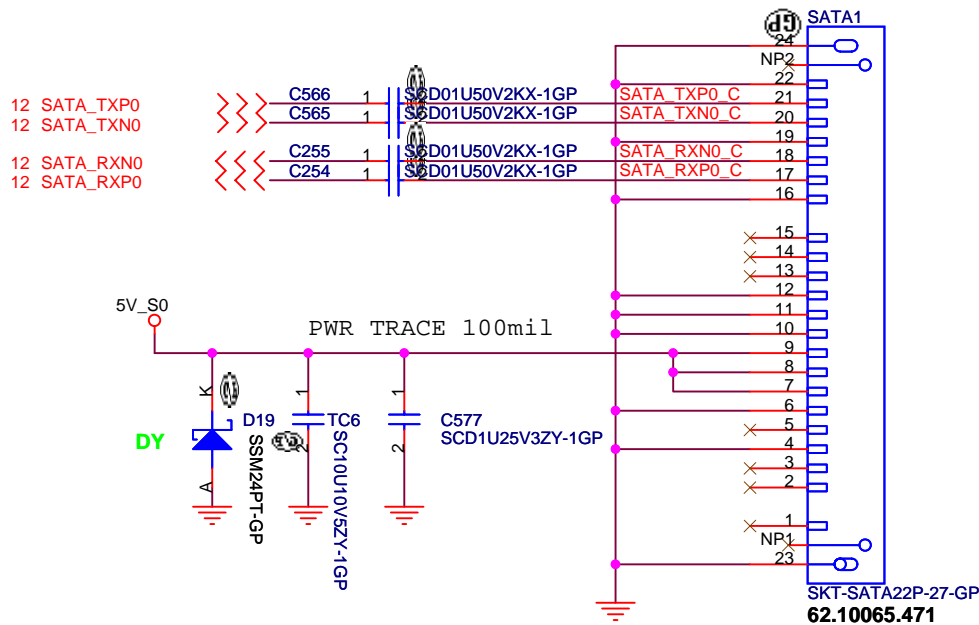
## DDC\_CLK & DATA level shift







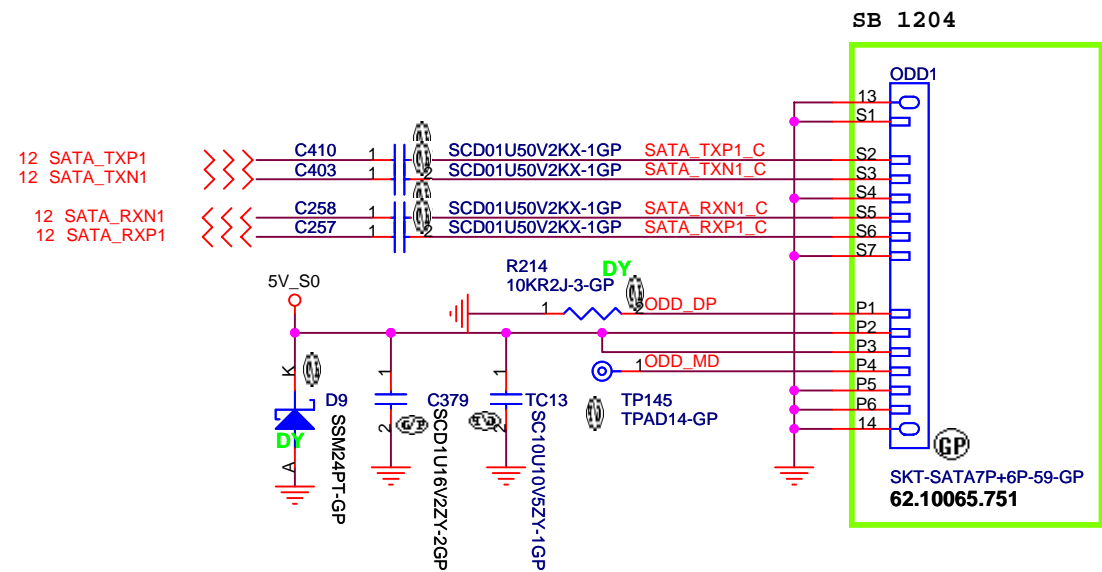
# SATA Connector



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Title			
<b>HDD CONN</b>			
Size	Document Number		Rev
	<b>JV50</b>		<b>SB</b>
Date:	Tuesday, December 16, 2008	Sheet 21 of	60

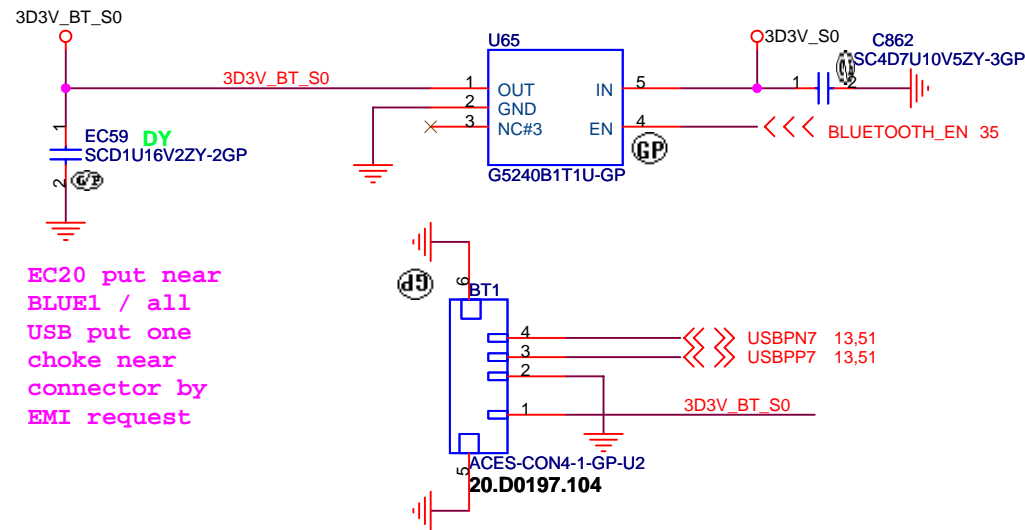
# ODD Connector



JV50

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
ODD			
Size	Document Number		Rev
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Date: Tuesday, December 16, 2008		Sheet 22 of 60	

# BLUETOOTH MODULE



JV50

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Title

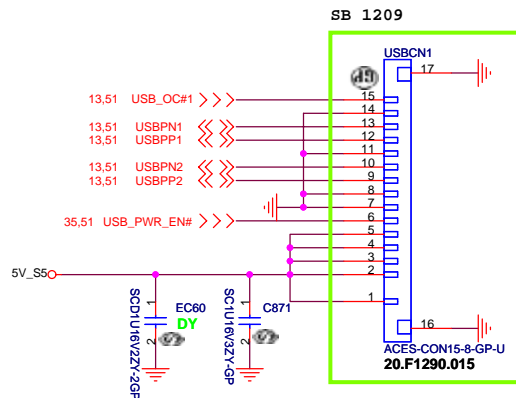
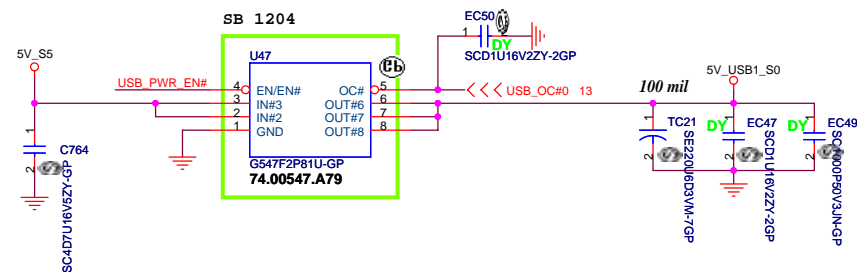
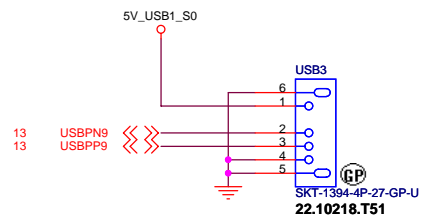
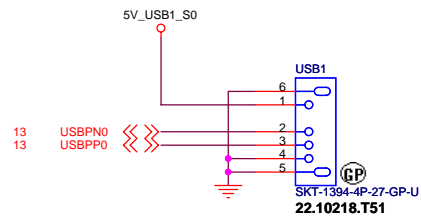
**BLUETOOTH**

Size Document Number Rev

**JV50**

SB

Date: Tuesday, December 16, 2008 Sheet 23 of 60



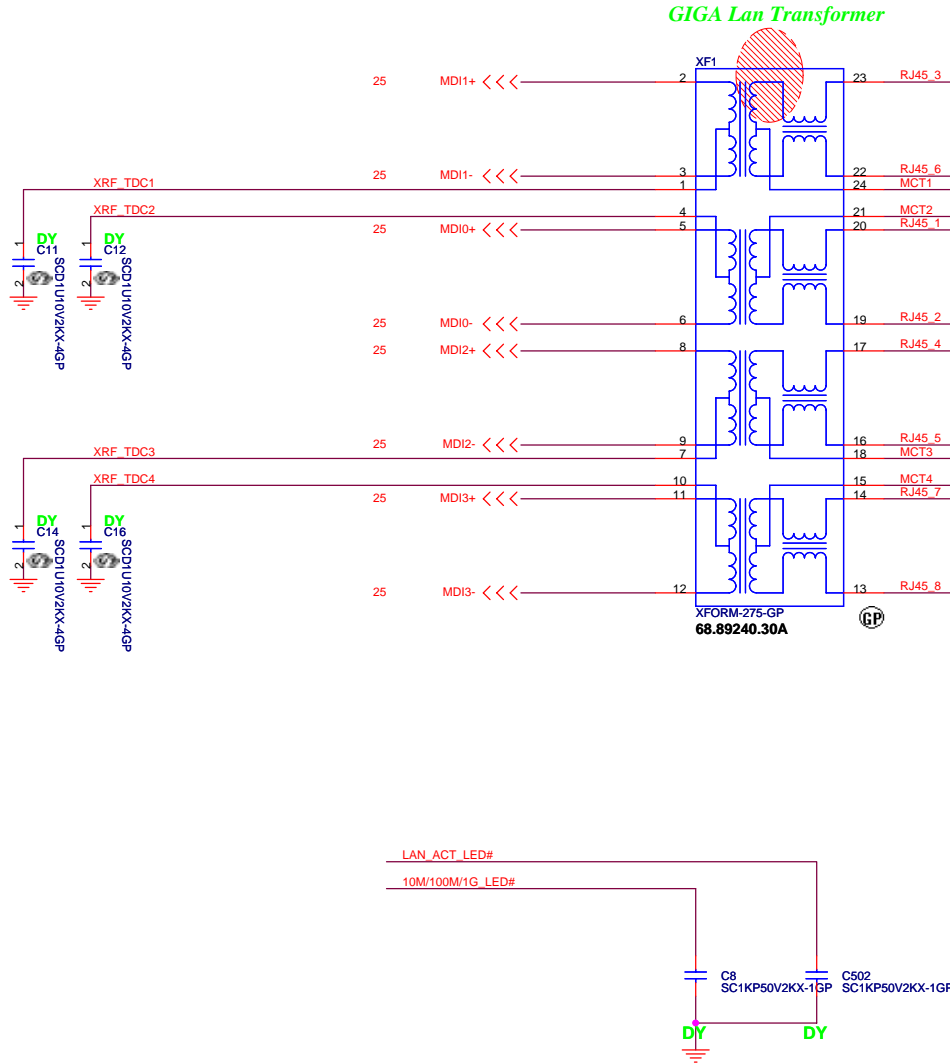
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<b>緯創資通</b>		<b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <b>USB CONN</b>			
Size	Document Number		Rev
	JV50		SB
Date: Tuesday, December 16, 2008 Sheet 24 of 60			

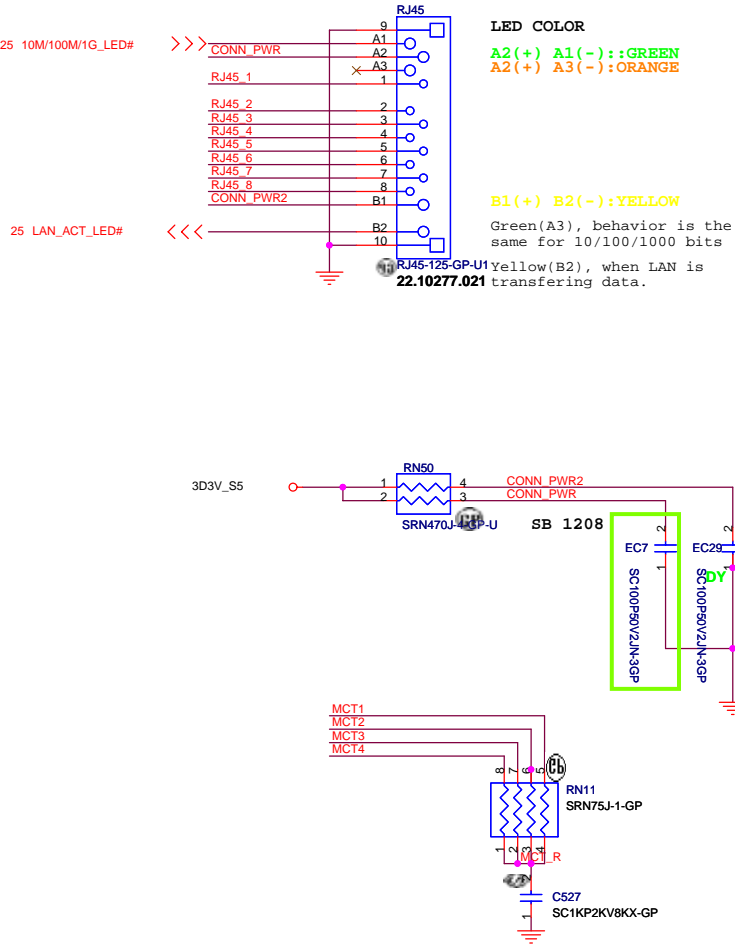


- 1.route on bottom as differential pairs.  
2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.  
3.No vias, No 90 degree bends.  
4.pairs must be equal lengths.  
5.6mil trace width, 12mil separation.  
6.36mil between pairs and any other trace.  
7.Must not cross ground moat,except  
RJ-45 moat.

# LAN Connector

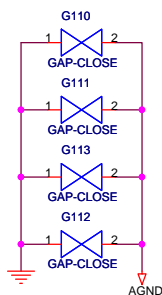
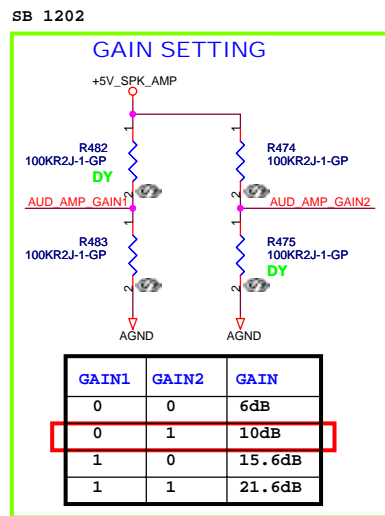
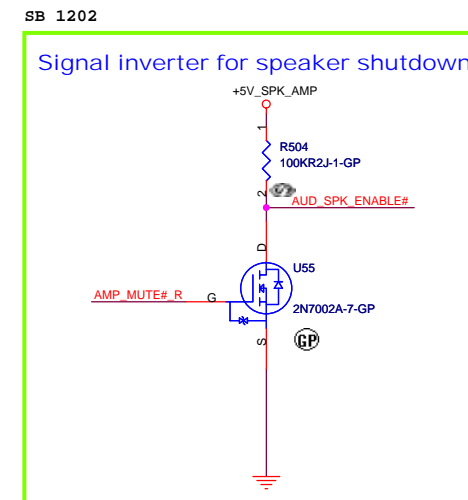
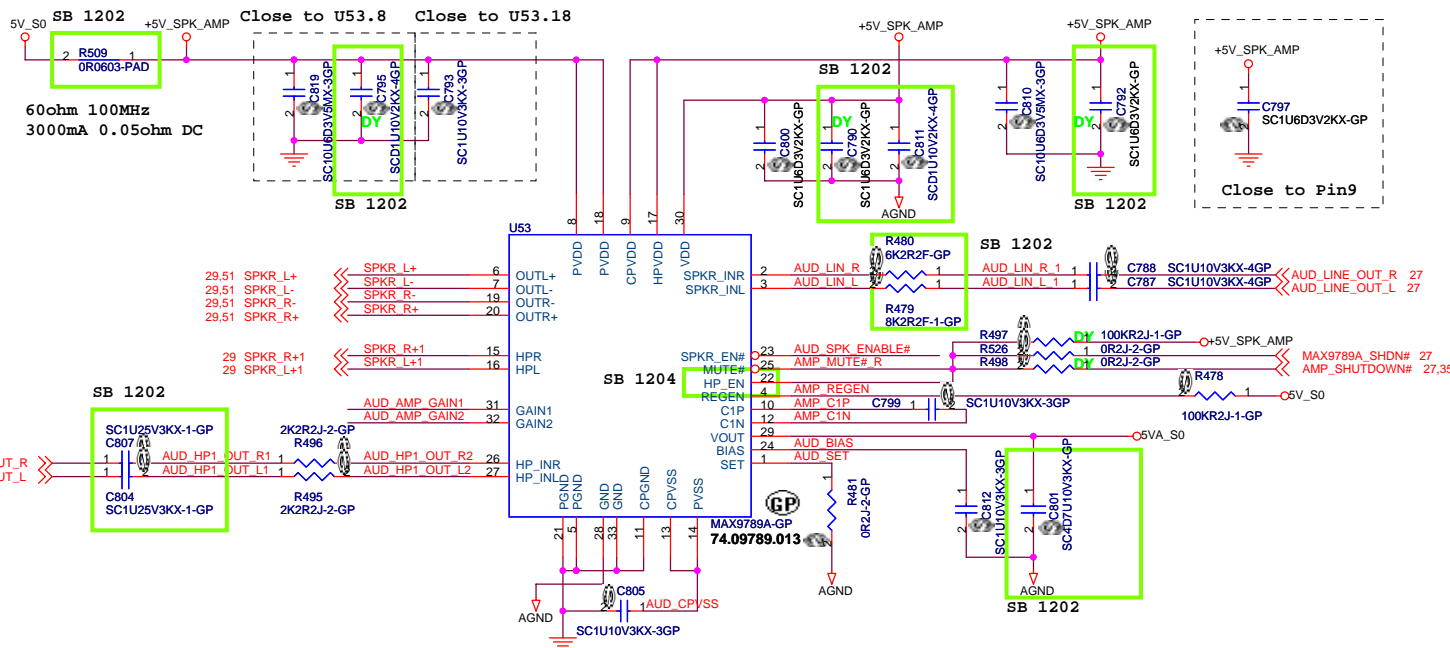


# LAN Connector





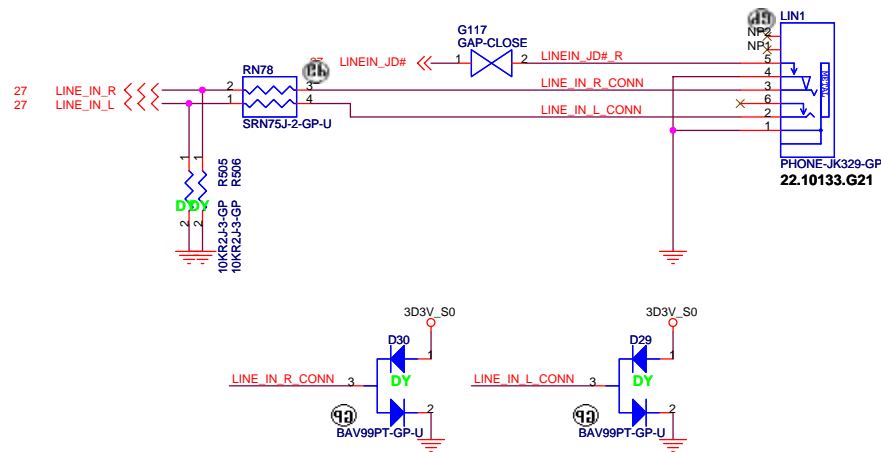




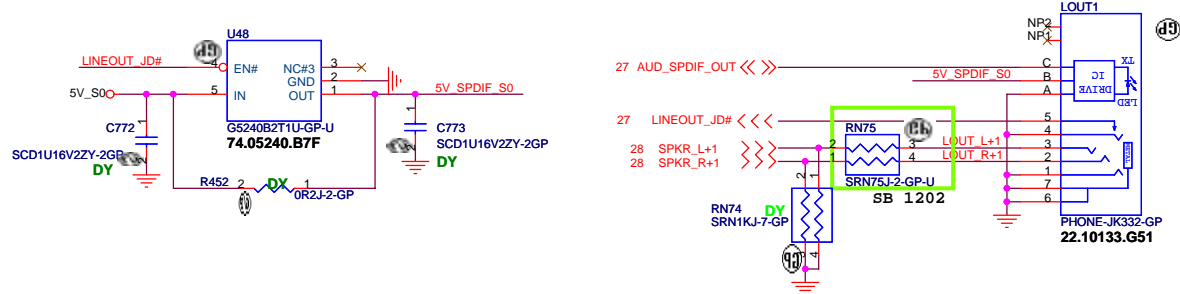
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Taipei Hsien 221, Taiwan, R.O.C.

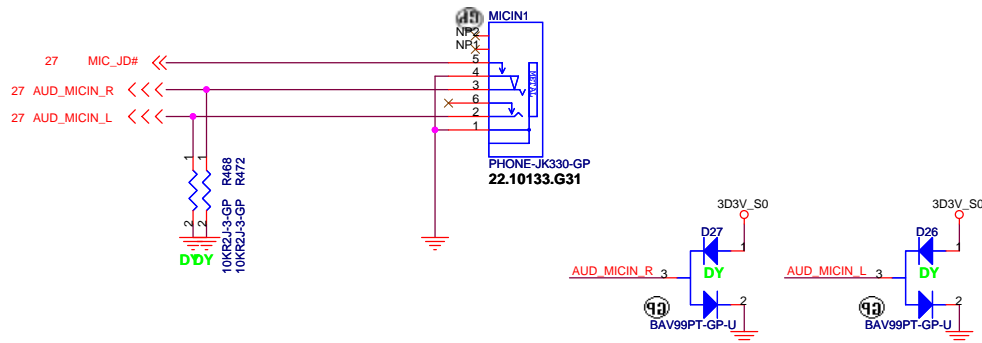
## LINE IN



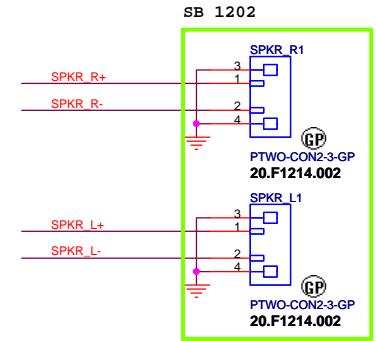
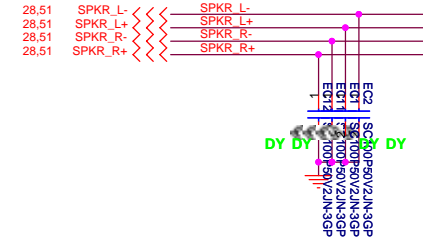
## LINE OUT



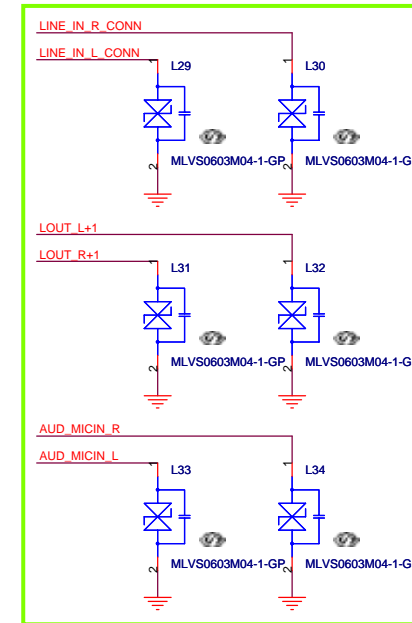
## MIC IN



## Internal Speaker

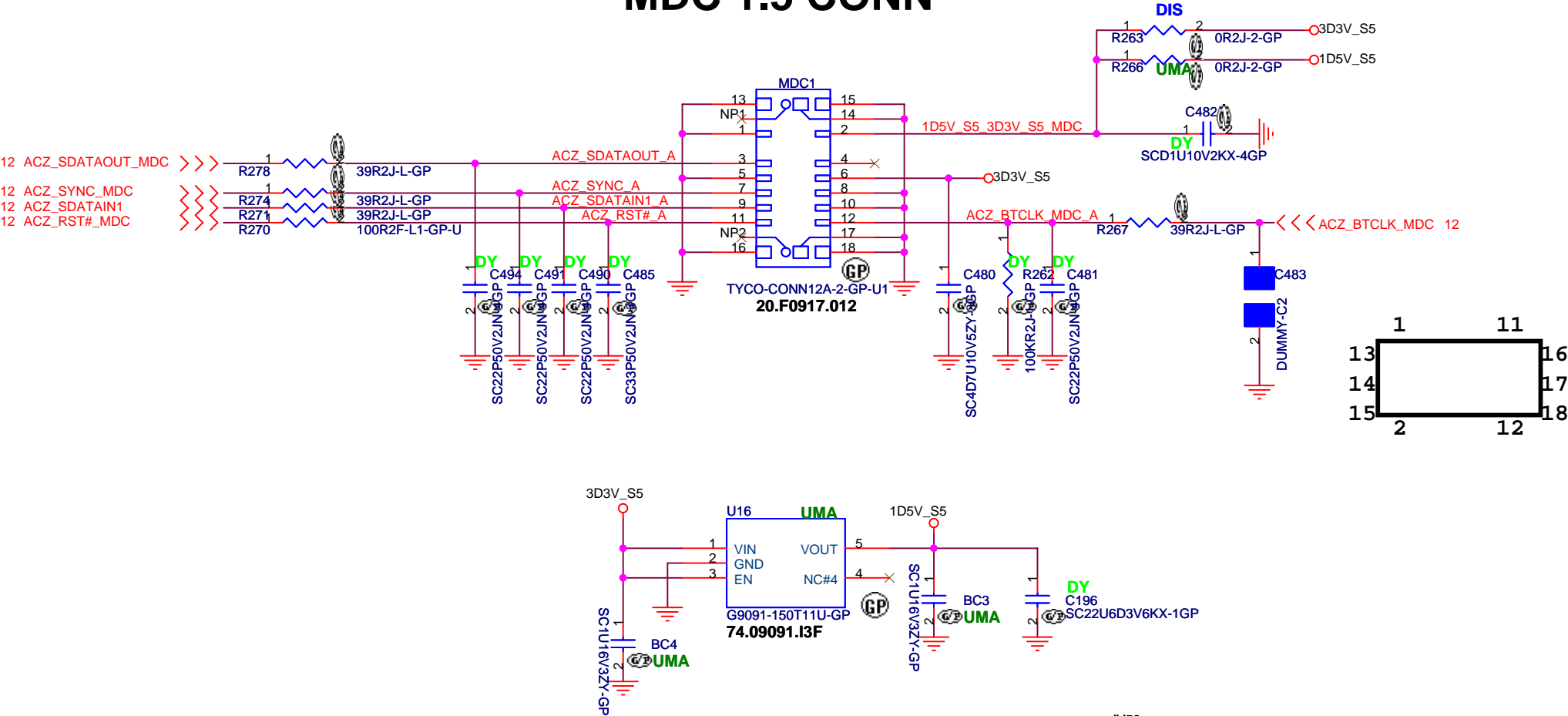


SB 1202



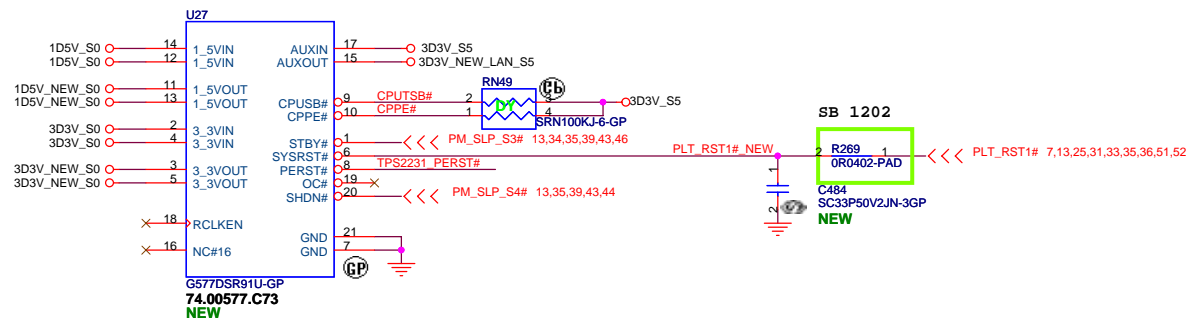
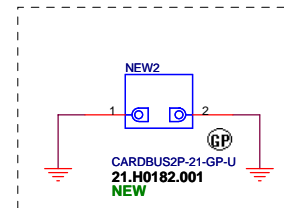
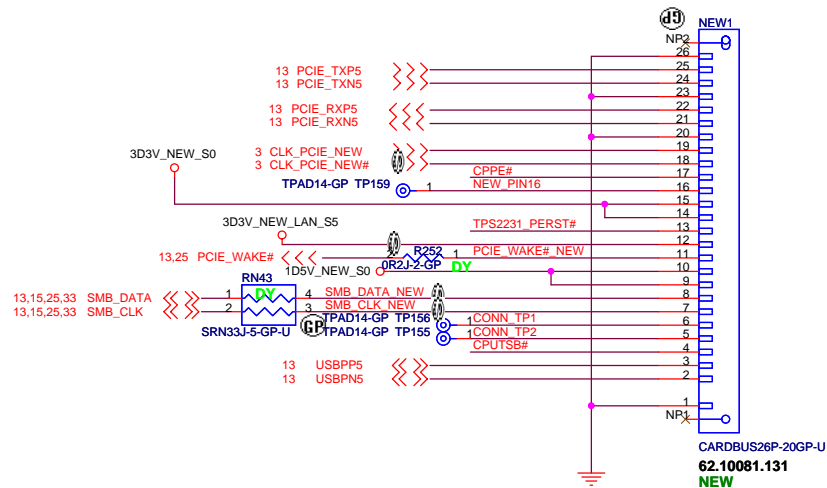
JV50

MDC 1.5 CONN

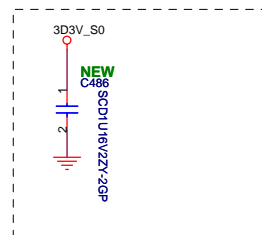


JV50

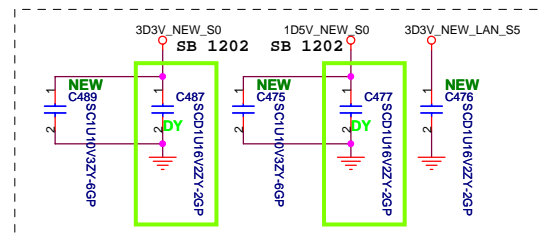




Place them Near to Chip



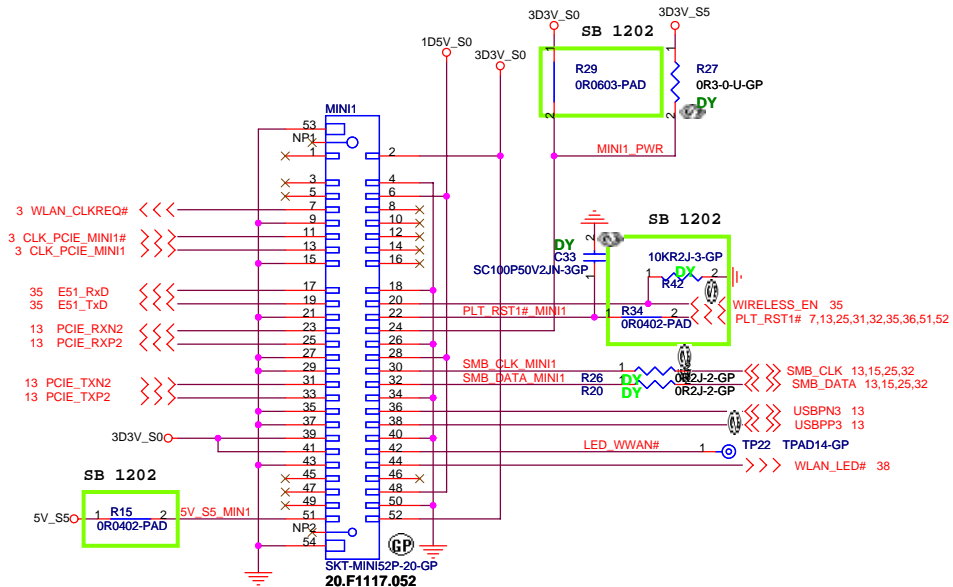
Place them Near to Connector



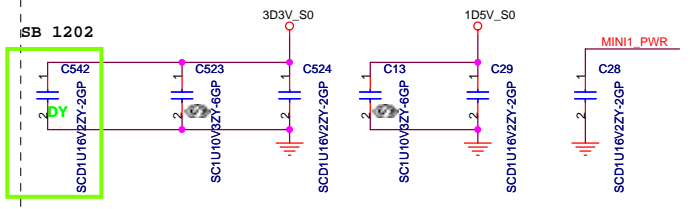
JV50

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<b>NEW CARD</b>			
Size	Document Number	Rev	SB
<b>JV50</b>			
Date: Tuesday, December 16, 2008		Sheet 32 of 60	

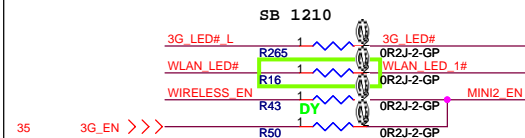
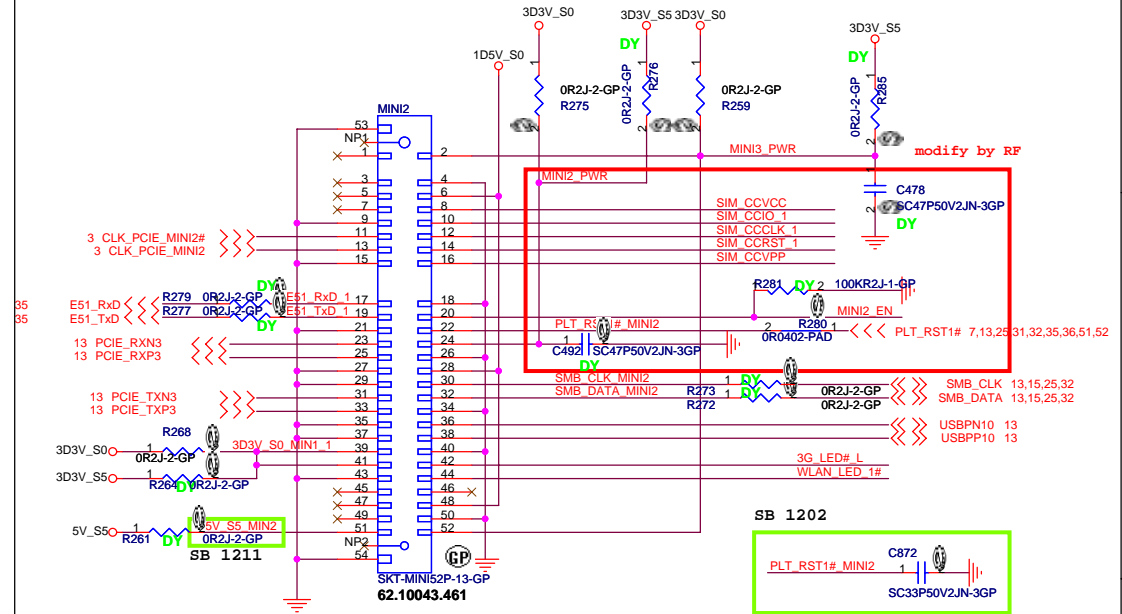
## *Mini Card Connector(WLAN)* *Support debug-card*



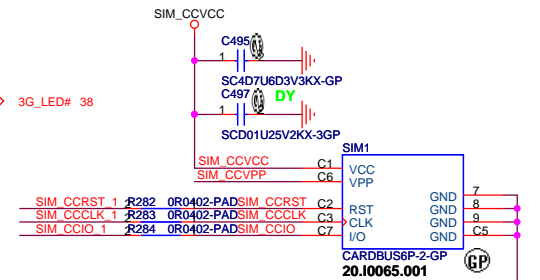
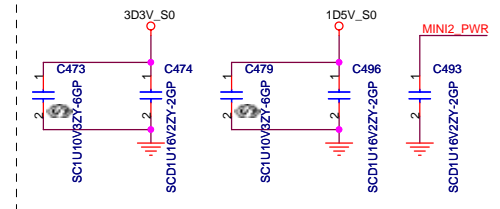
Place near MINI1



### ***Mini Card Connector(Robson2 and 3G)***



Place near MINIC2



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Title
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**MINI CARD**

Size	A3
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Document Number
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## JV50

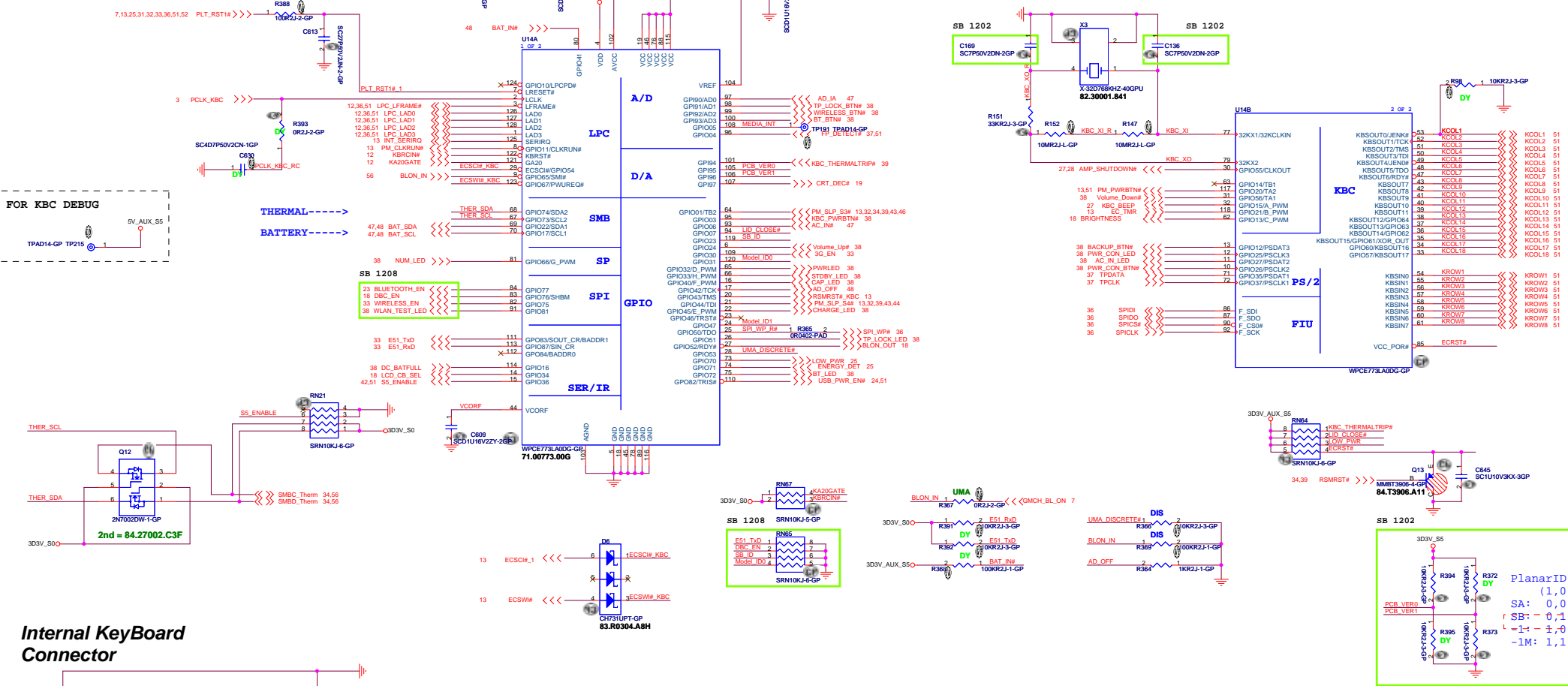
Date: Tuesday, December 16, 2008

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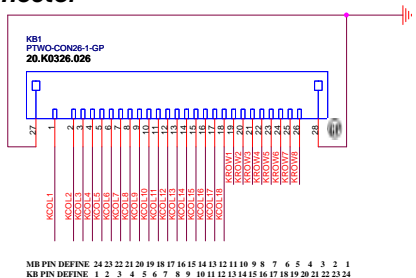
Rev  
SR







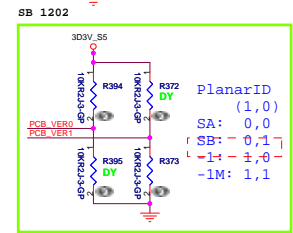
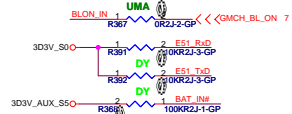
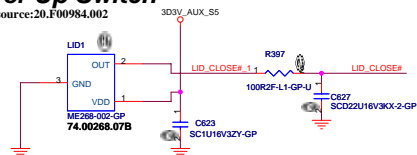
### Internal KeyBoard Connector



MB PIN DEFINE	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1
KB PIN DEFINE	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24

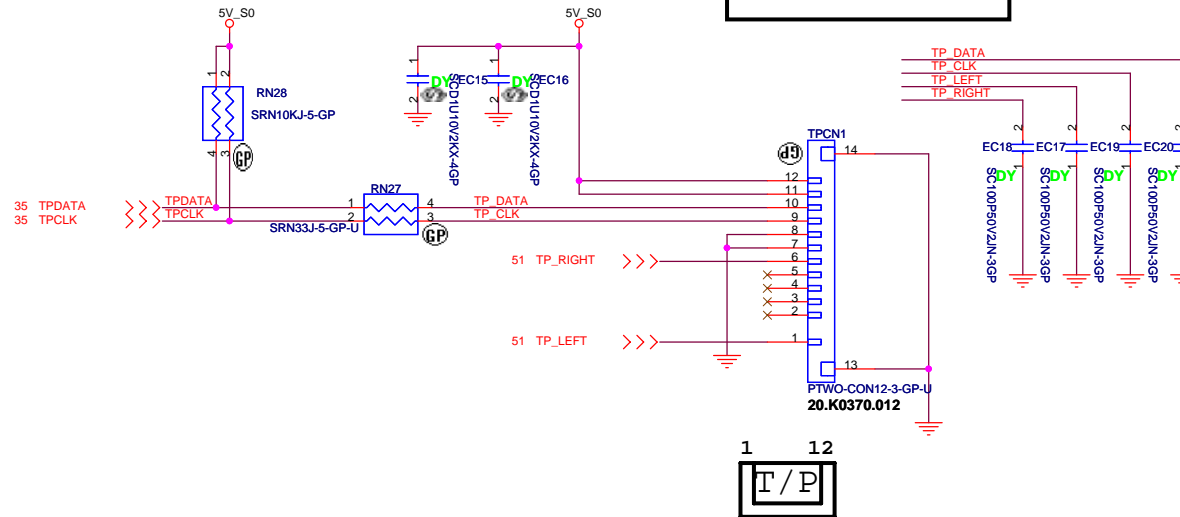
## Cover Up Switch

2nd source:20.F00984.002

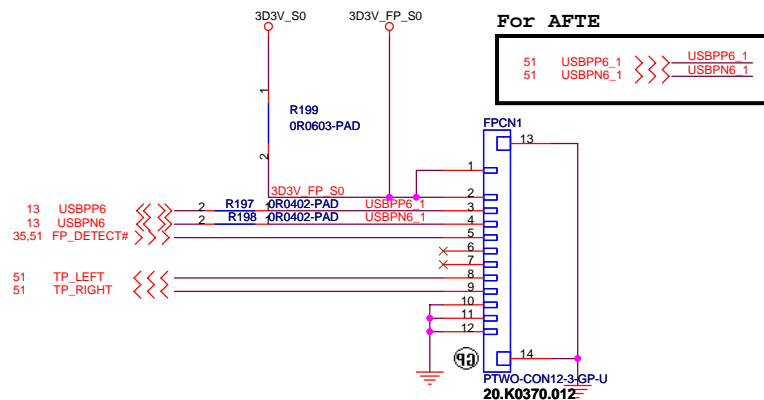




# TOUCH PAD



# Finger printer



JV50

**Power LED**

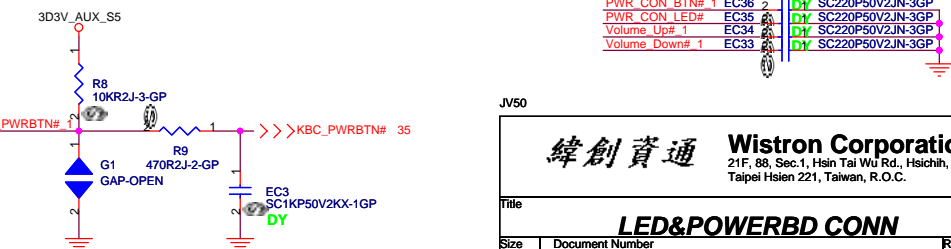
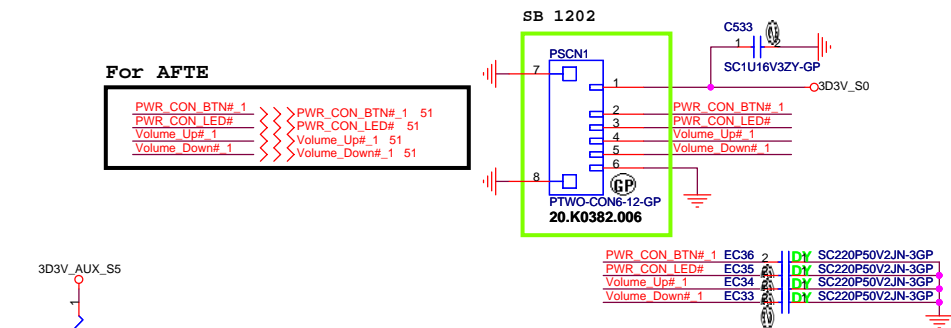
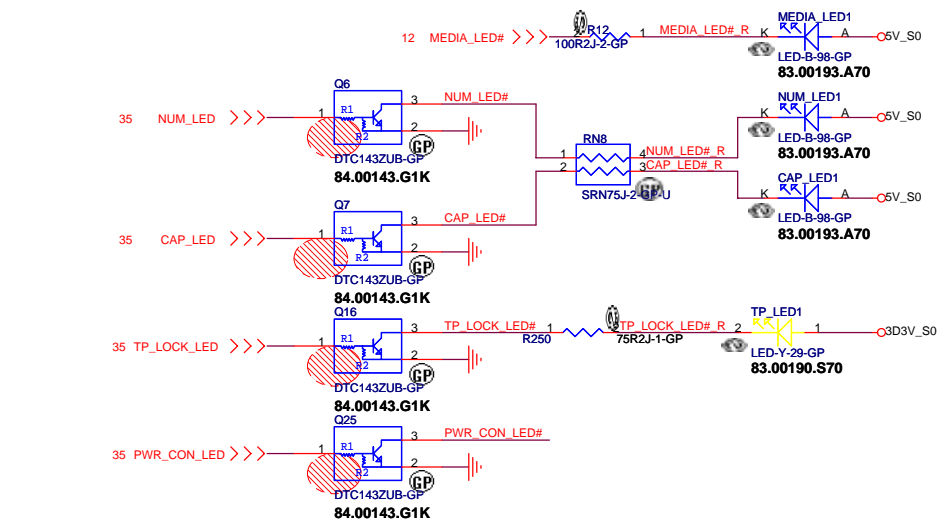
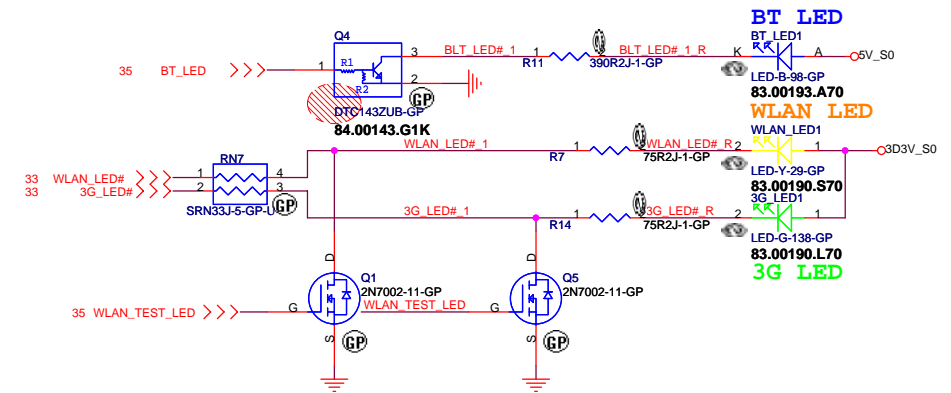
FRONT_PWRLED# Q	4
STDBY_LED# Q	3
DC_BATFULL# Q	2
CHARGE_LED# Q	1

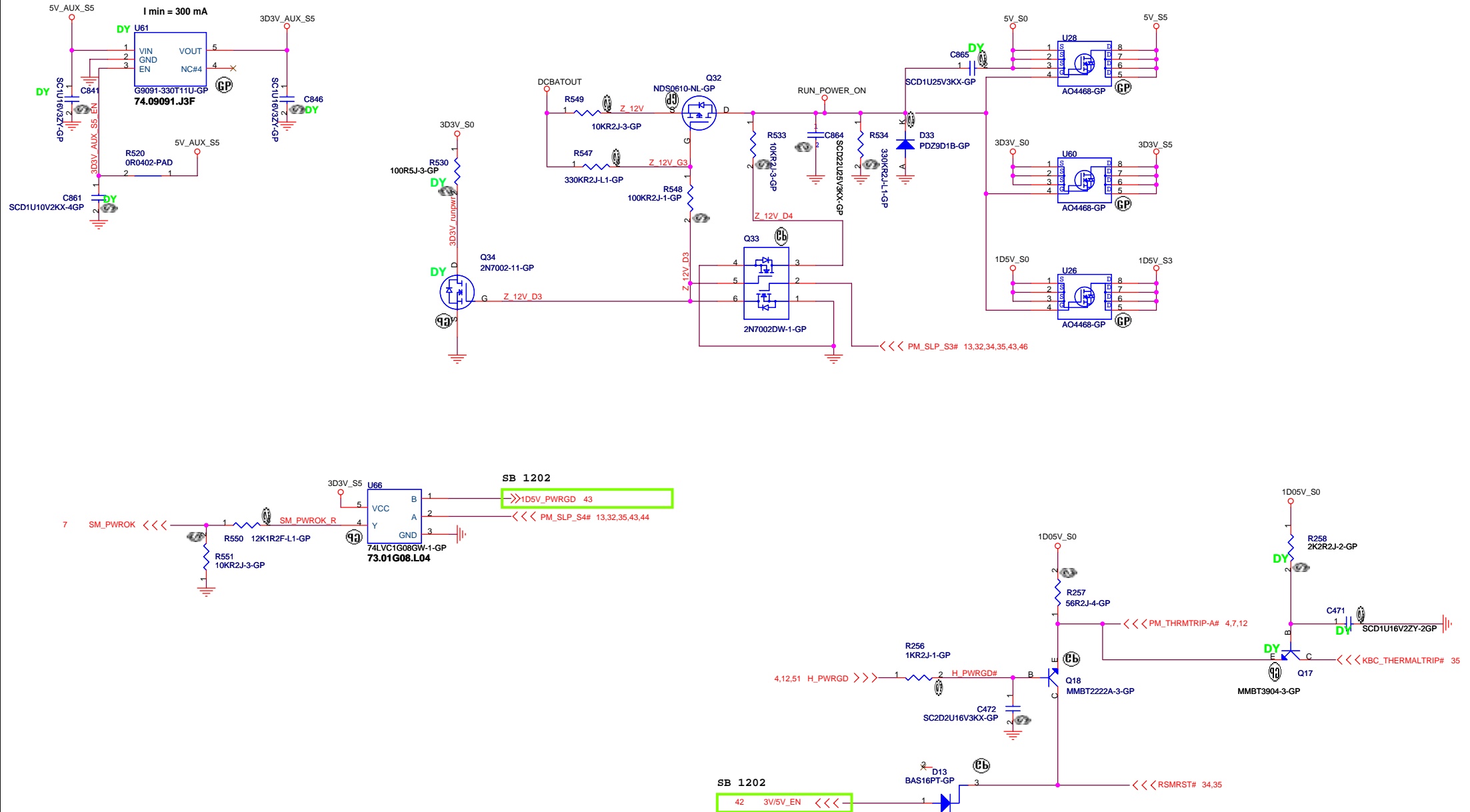
LED-OB-2-GP  
83.19223.A70

**Charger LED**

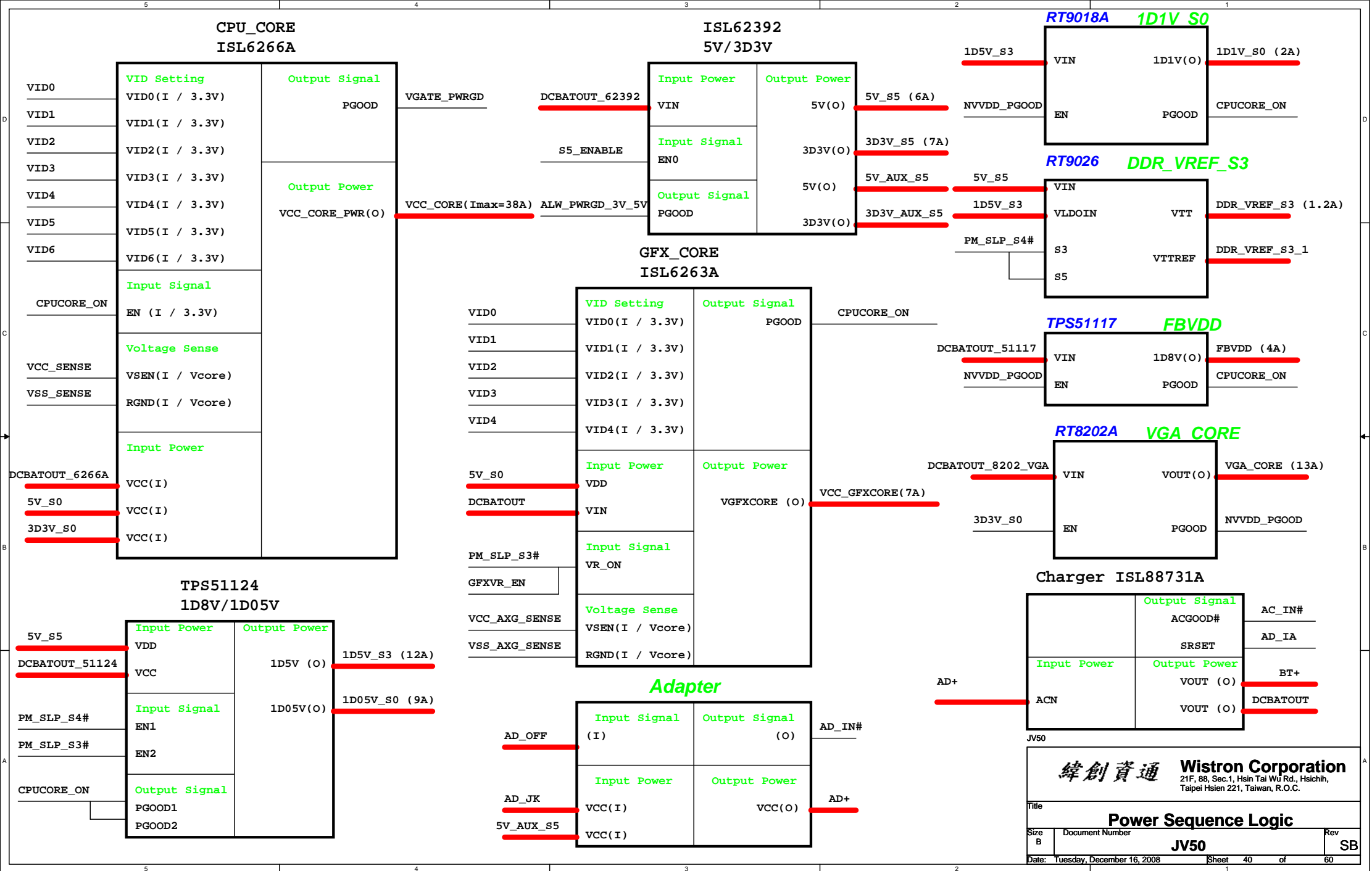
DC_BATFULL# R	3
CHARGE_LED# R	4

LED-OB-2-GP  
83.19223.A70

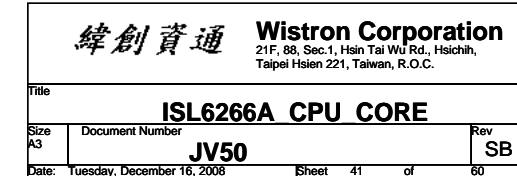




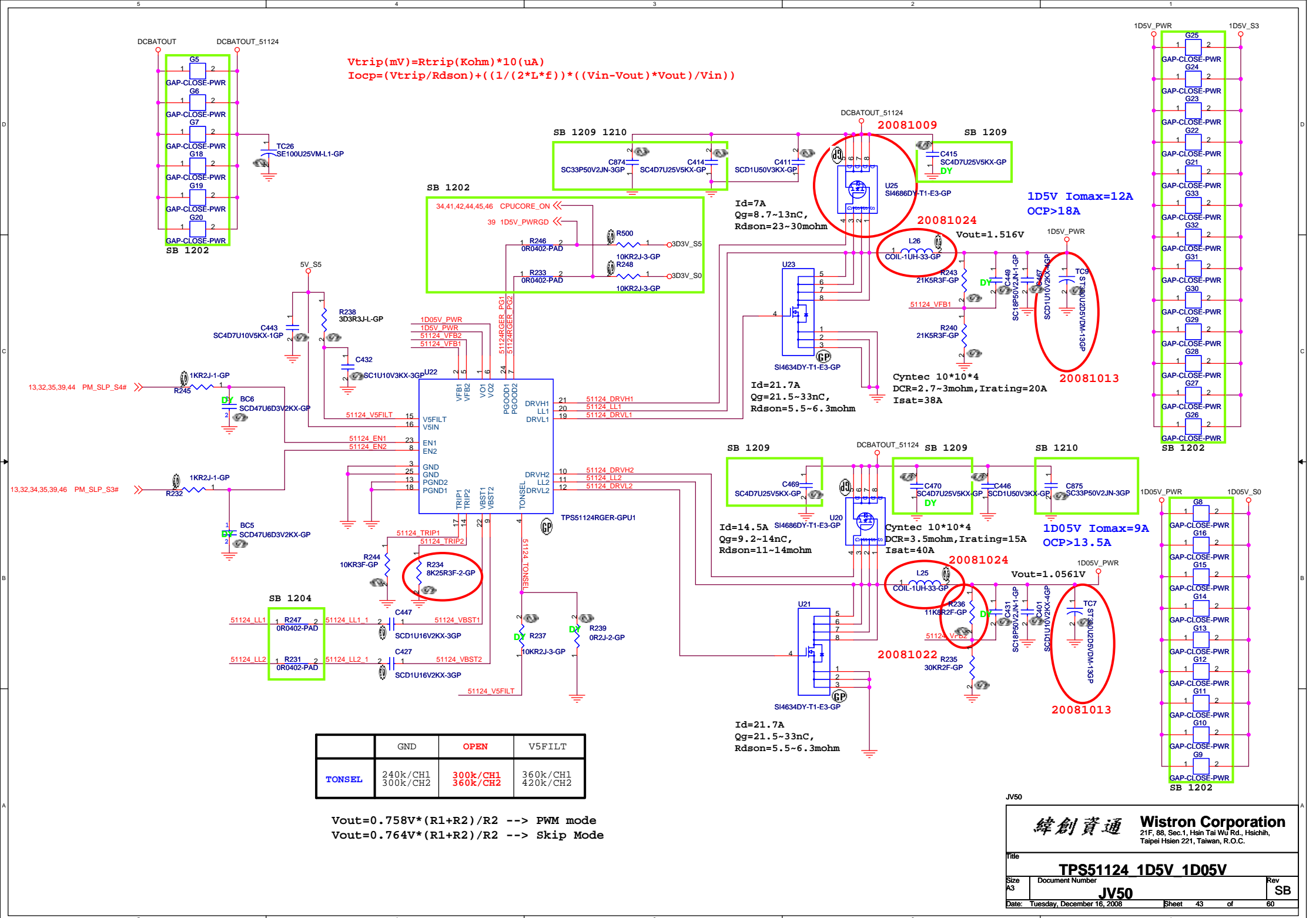
JV50

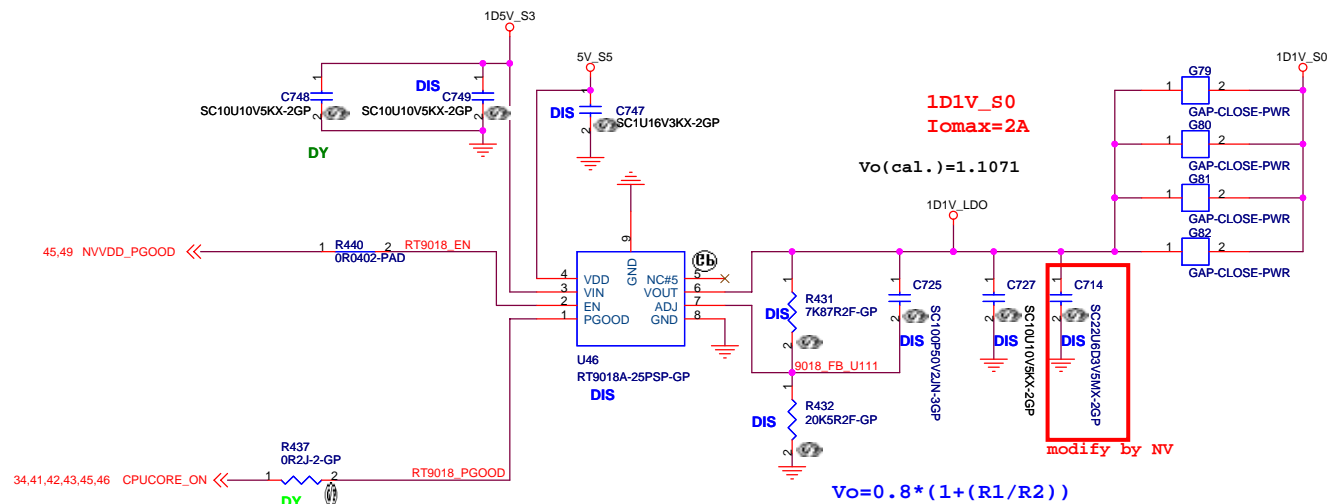
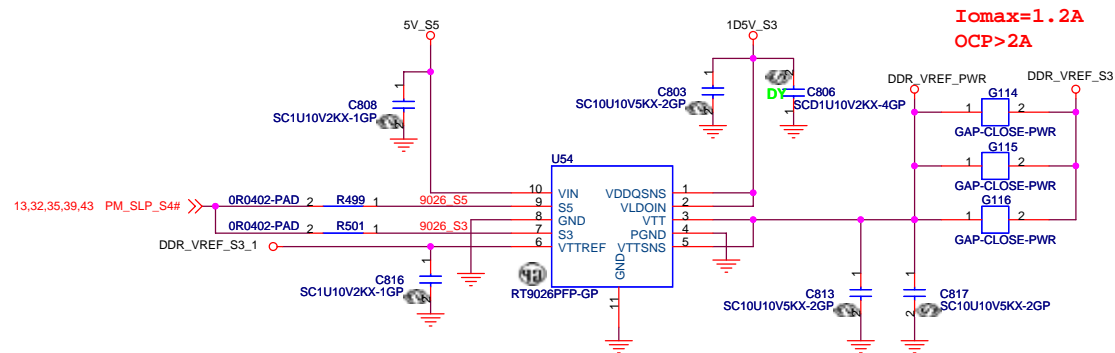








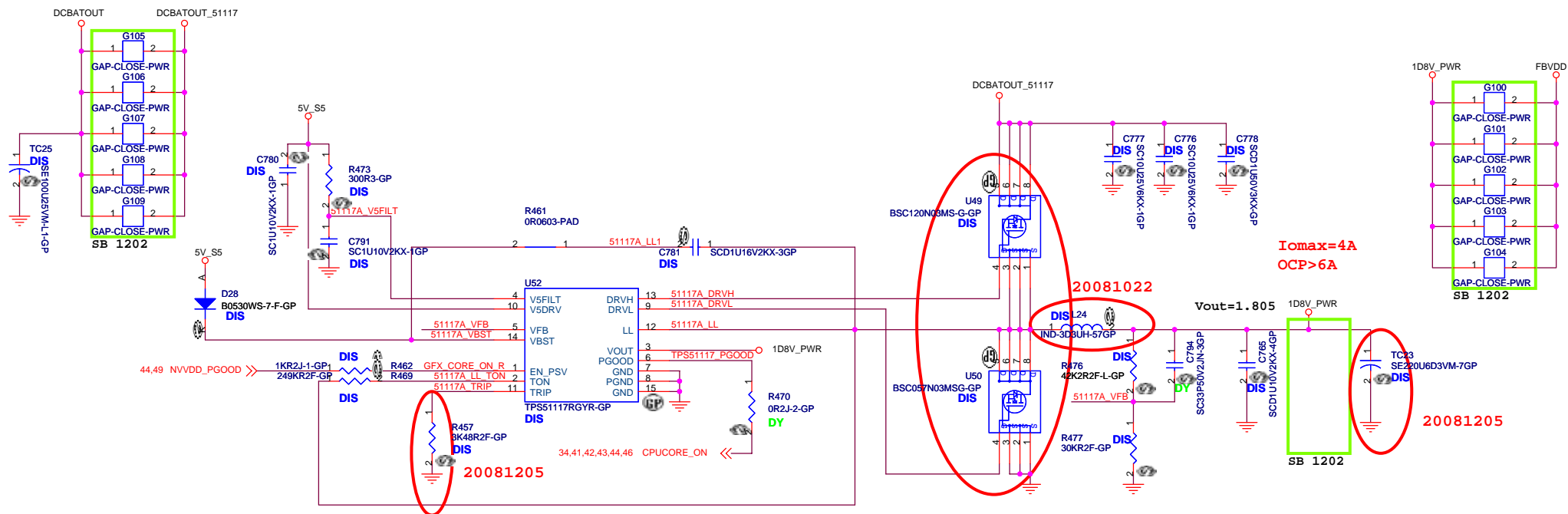




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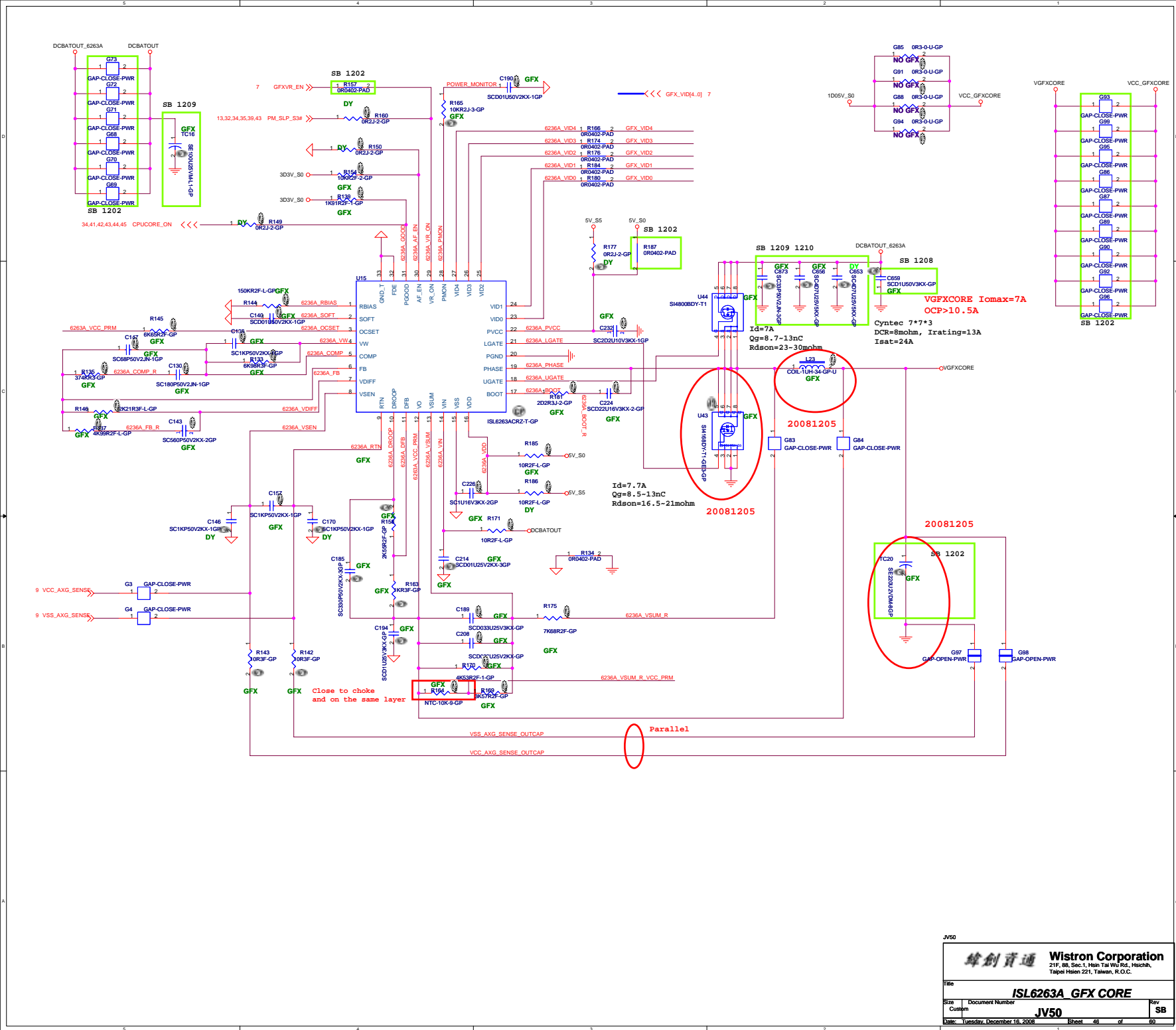
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Size	Document Number	JV50	
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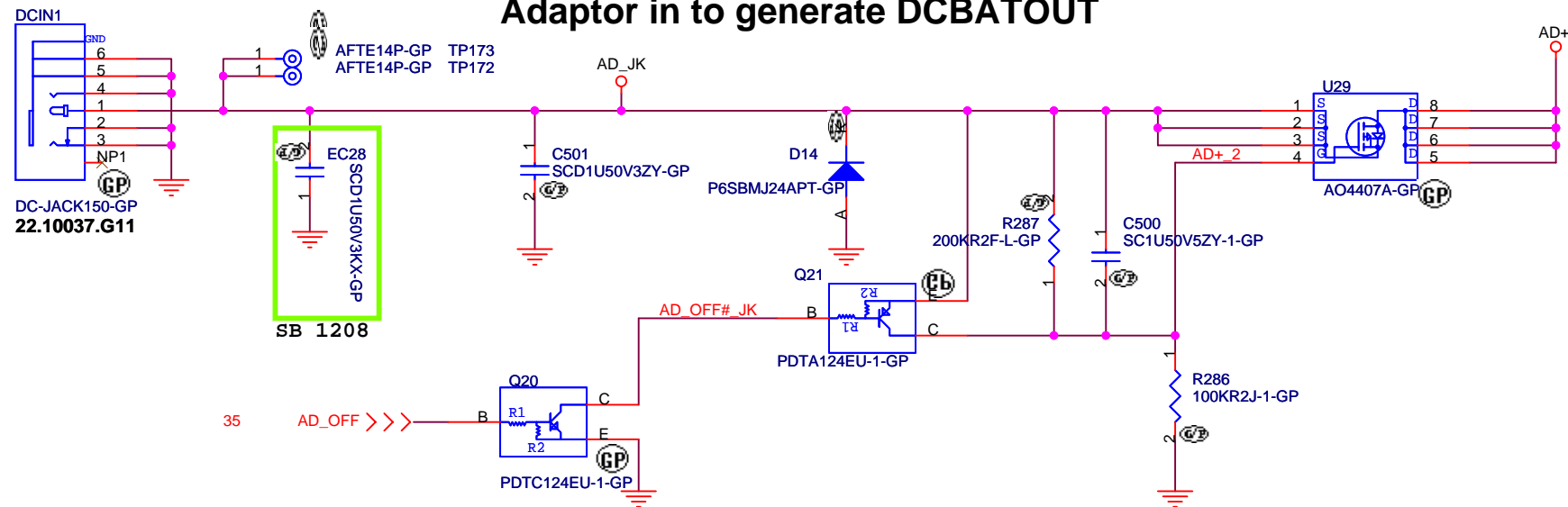
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Size	Document Number	Rev
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Date: Tuesday, December 16, 2008		
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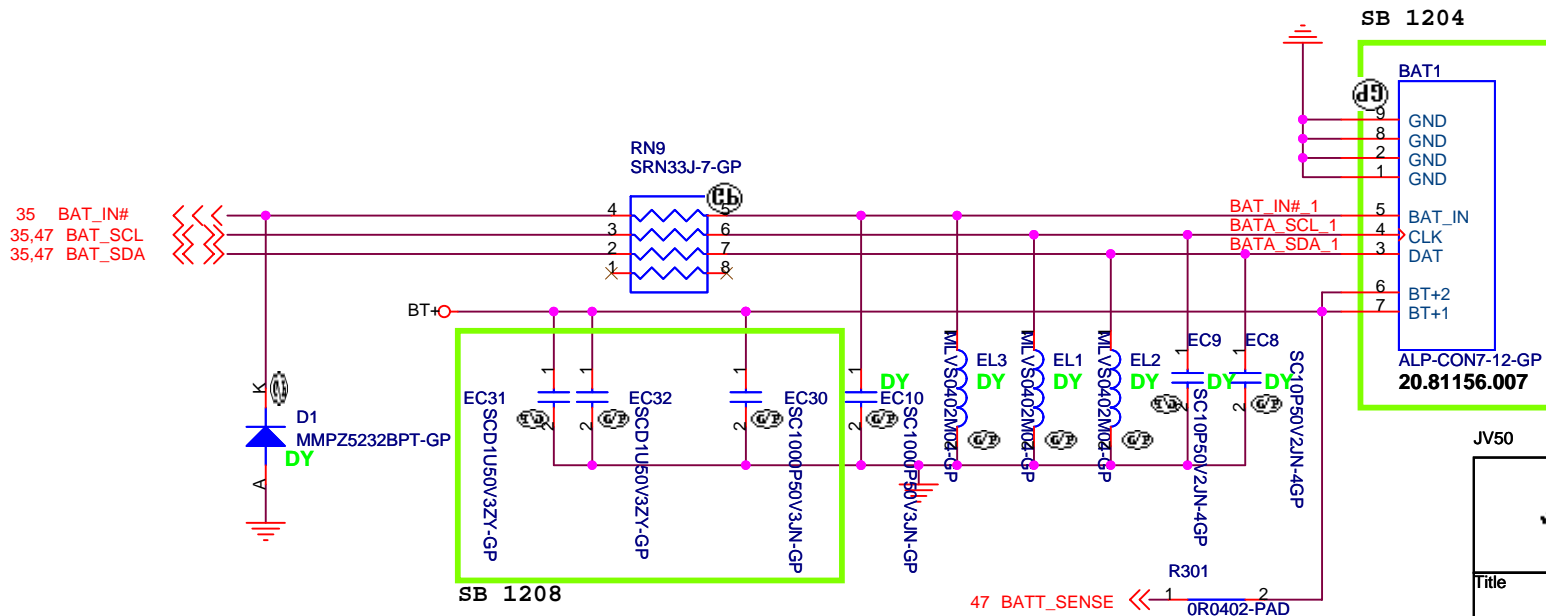




## Adaptor in to generate DCBATOUT



## BATTERY CONNECTOR



For AFTE

51 BATA\_SDA\_1 >>> BATA\_SDA\_1  
51 BATA\_SCL\_1 >>> BATA\_SCL\_1  
51 BAT\_IN#\_1 >>> BAT\_IN#\_1

緯創資通

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Title

**AD/BATT CONN**

Size

Document Number

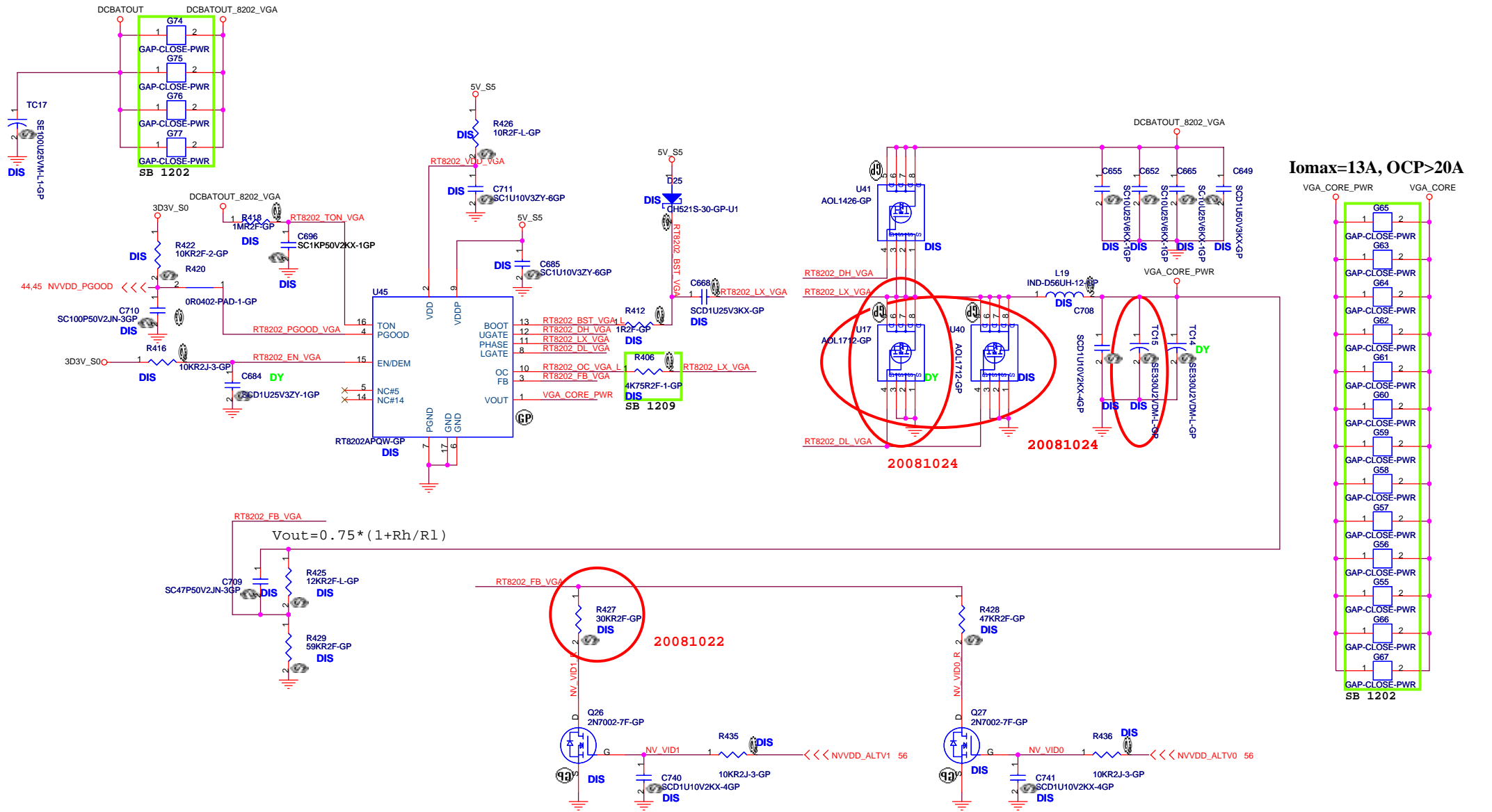
**JV50**

Rev

**SB**

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Iomax=13A, OCP>20A

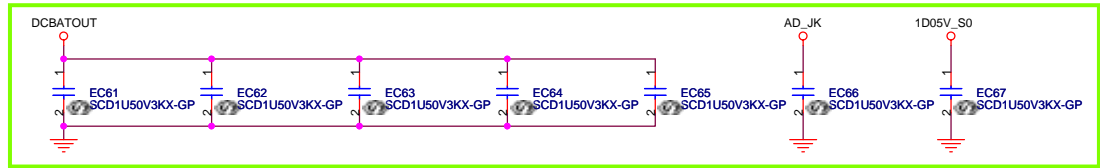
$$V_{out} = 0.75 * (1 + R_h / R_l)$$

N10M-GE1		
ALTV1	ALTV0	Vout
0	0	0.90V
0	1	1.09V
1	0	1.2V

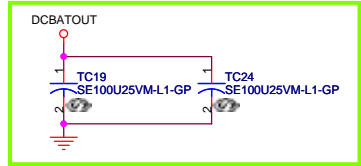
20081024

JV50

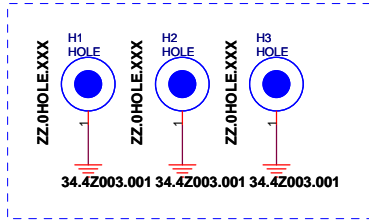
SB 1208



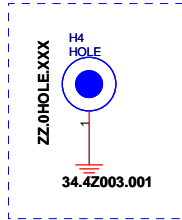
SB 1209



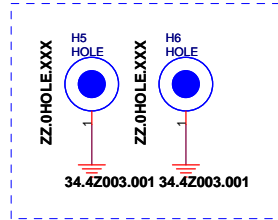
CPU



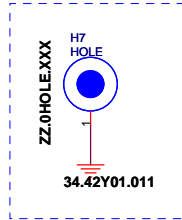
NB



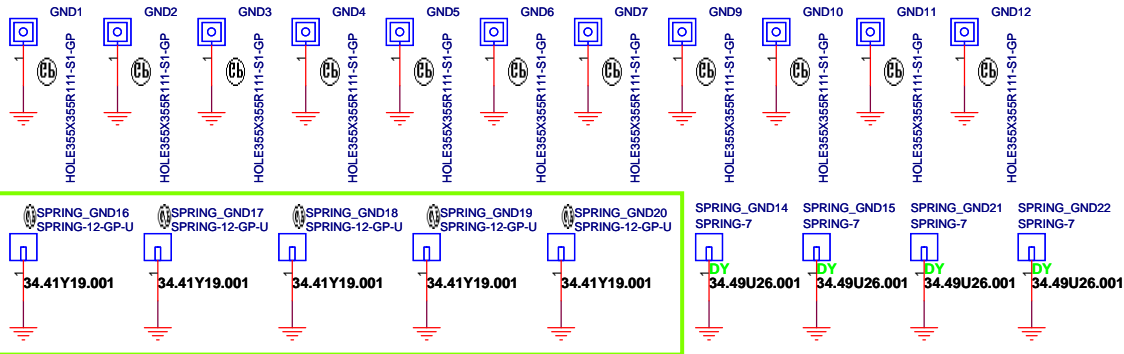
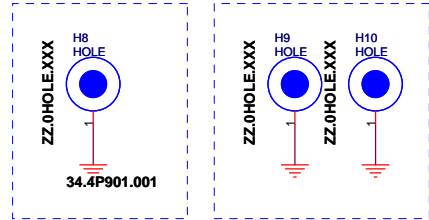
VGA



MDC



MINICARD

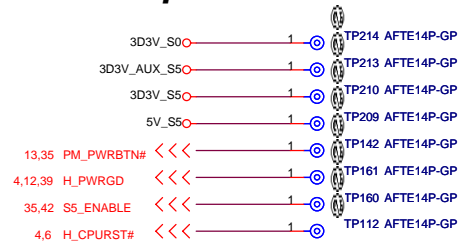


SB 1208

JV50

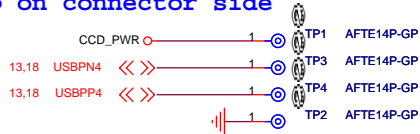
<b>緯創資通</b>		<b>Wistron Corporation</b>	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
<b>EMI/Spring/Boss</b>			
Size	Document Number		Rev
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## Check test point

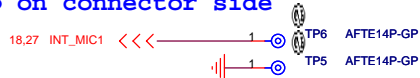


Test Point放在Dimm Door打開可量測處

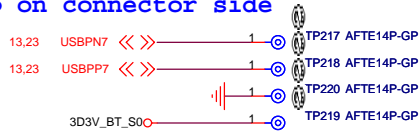
## CCD1 Conn. Test Point keep on connector side



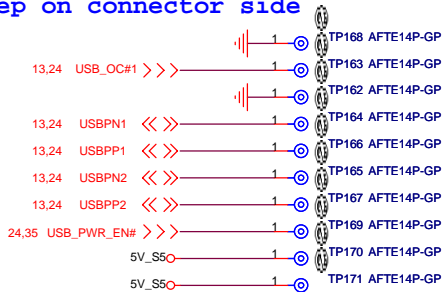
## AMIC1 Conn. Test Point keep on connector side



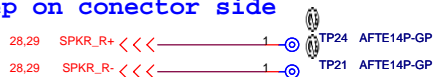
## BT1 Conn. Test Point keep on connector side



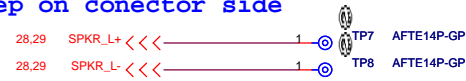
## USBCN1 Conn. Test Point keep on connector side



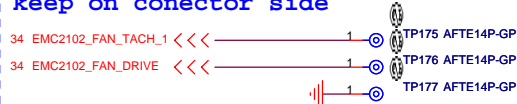
## SPKR\_R1 Conn. Test Point keep on connector side



## SPKR\_L1 Conn. Test Point keep on connector side



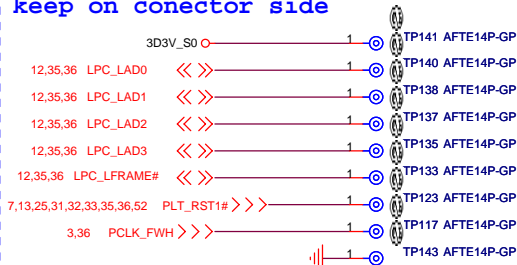
## FAN1 Conn. Test Point keep on connector side



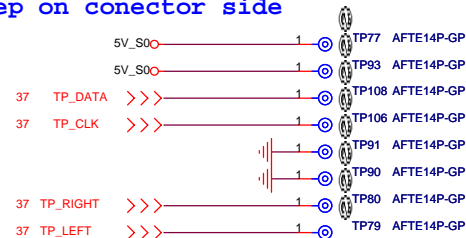
## KB1 Conn. Test Point keep on connector side



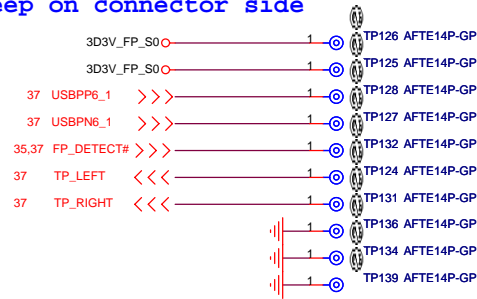
## DB1 Conn. Test Point keep on connector side



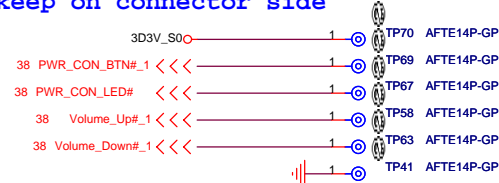
## TPCN1 Conn. Test Point keep on connector side



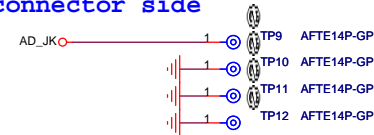
## FPCN1 Conn. Test Point keep on connector side



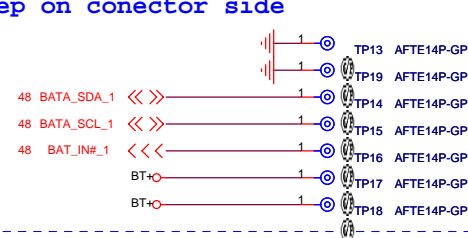
## PSCN1 Conn. Test Point keep on connector side



## DCIN1 Conn. Test Point keep on connector side



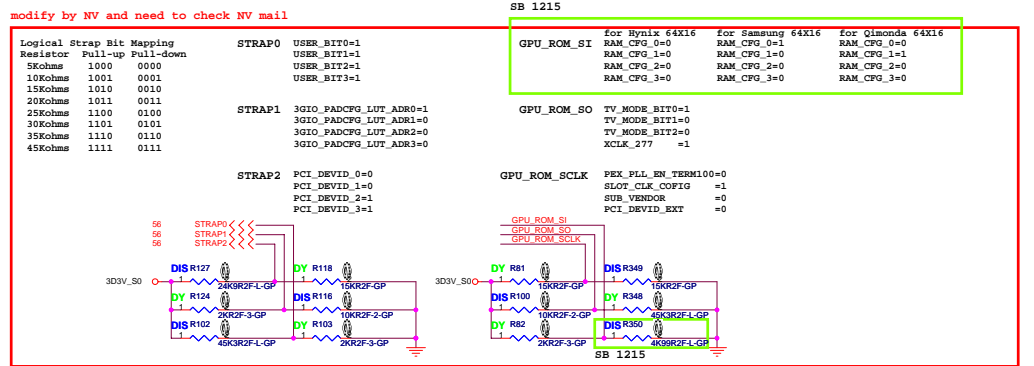
## TPCN1 Conn. Test Point keep on connector side



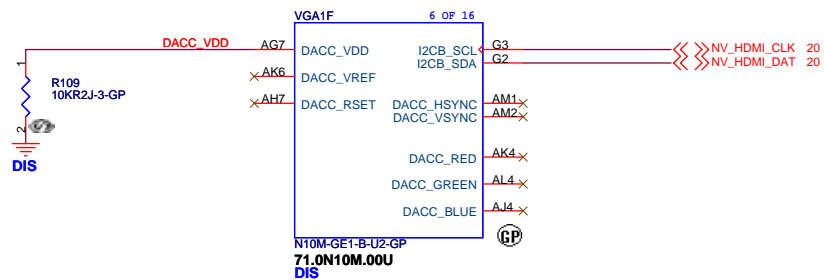
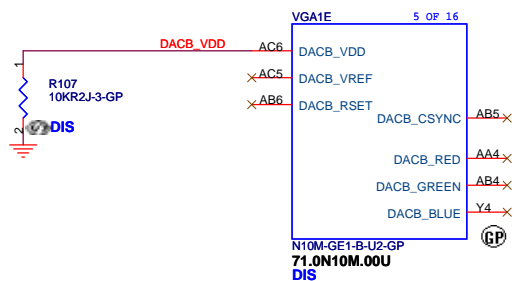
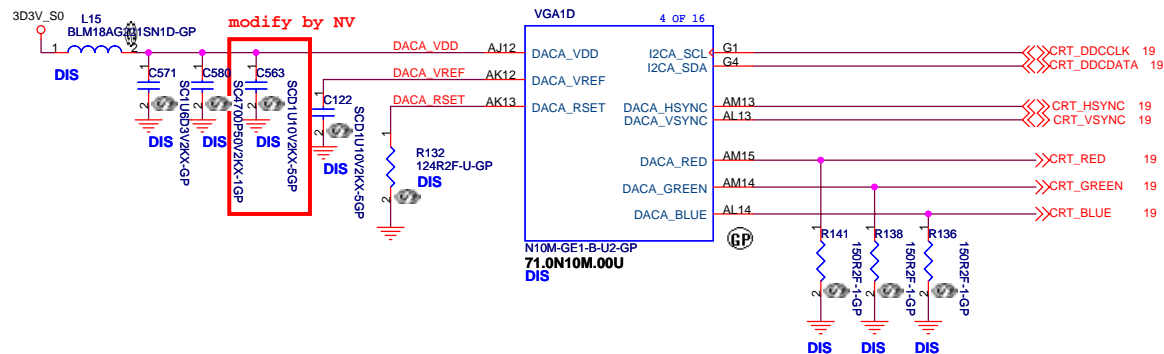
JV50

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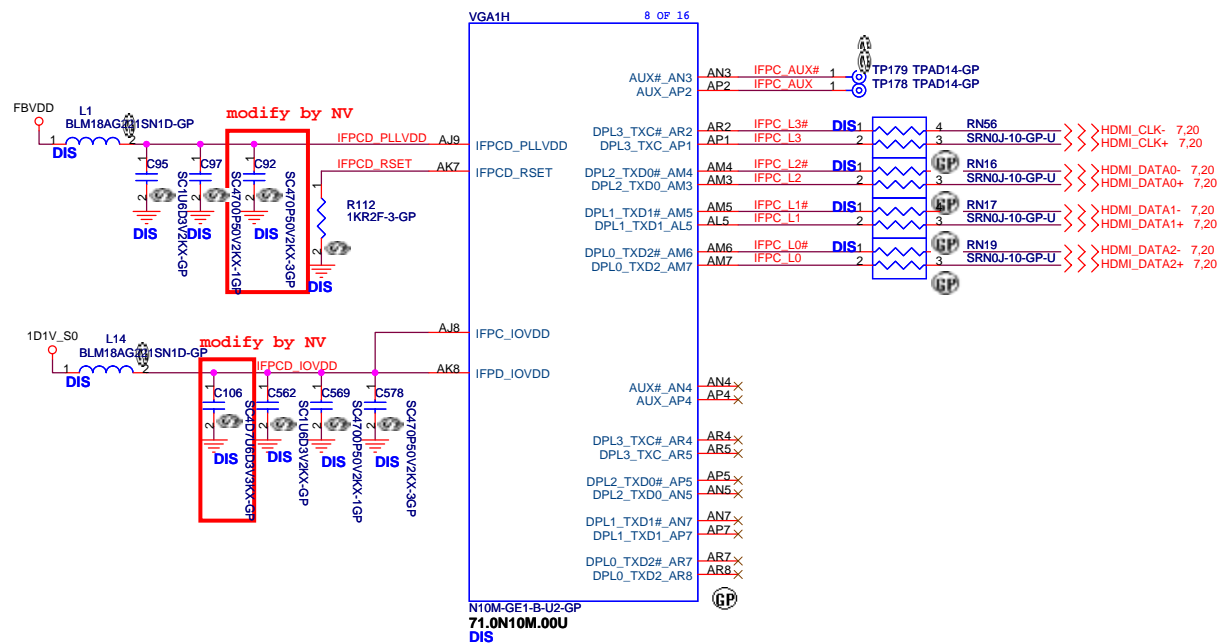
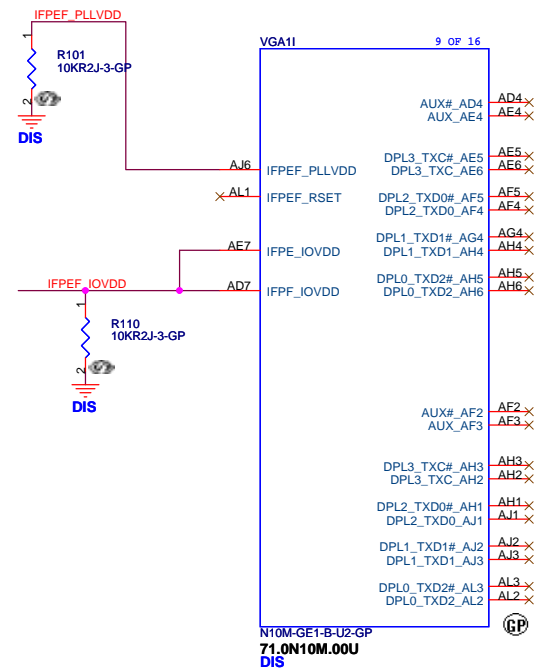
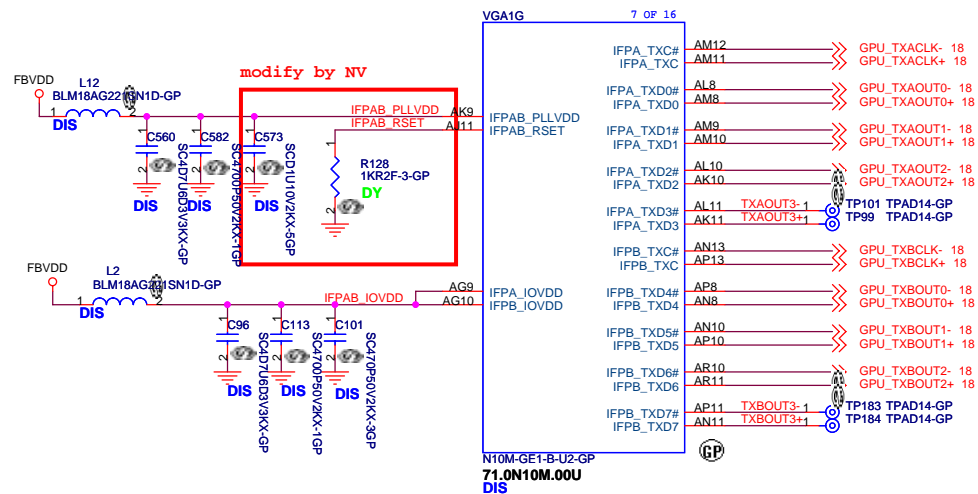




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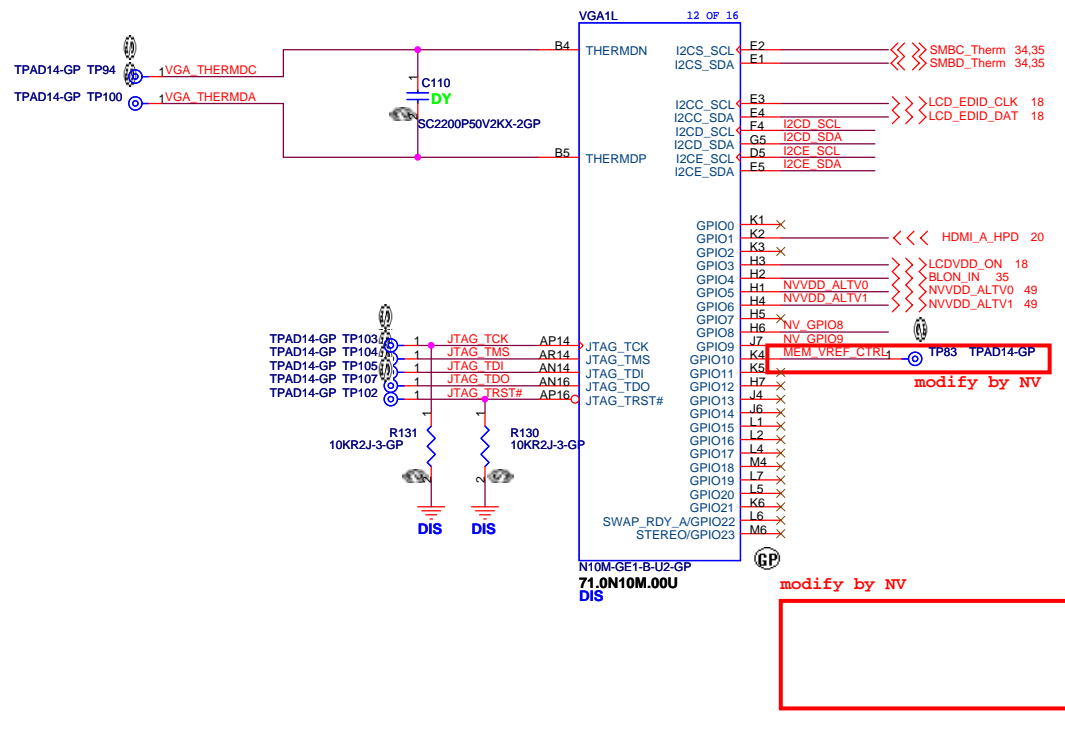
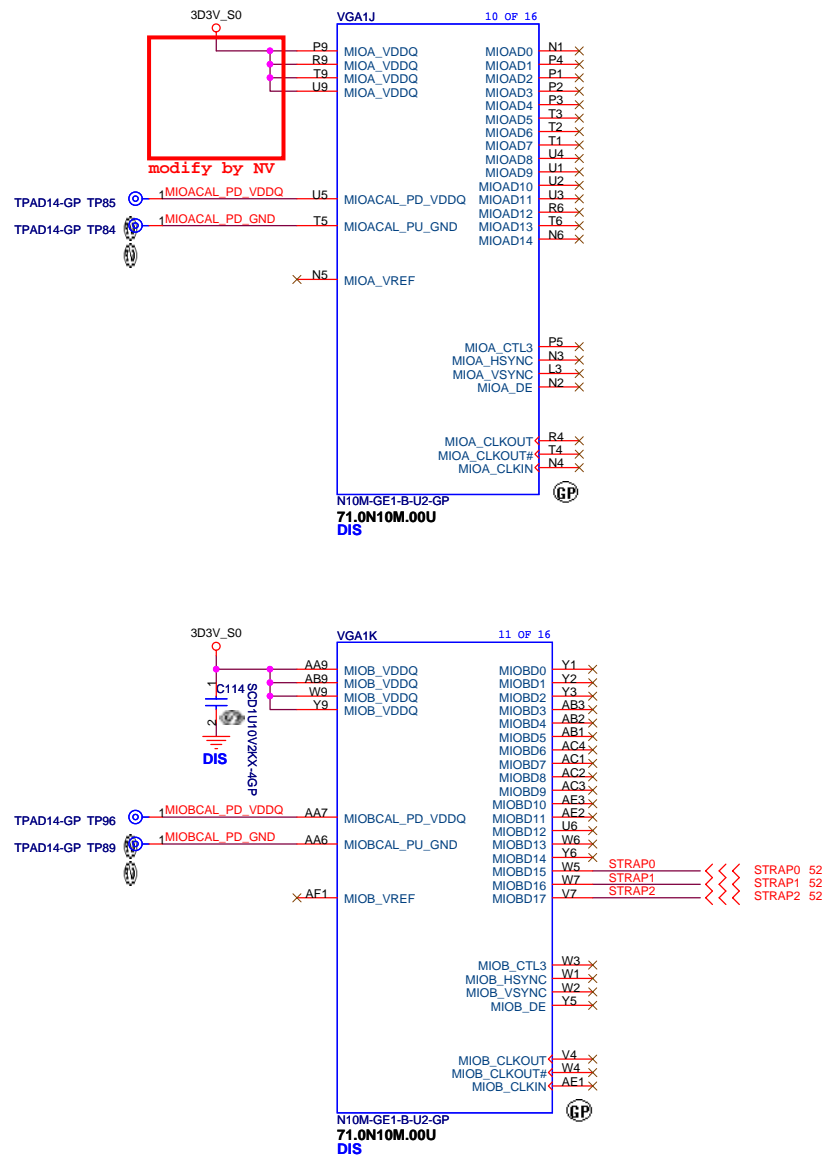
<b>緯創資通</b>		<b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
<b>N10M(3/6) DAC</b>			
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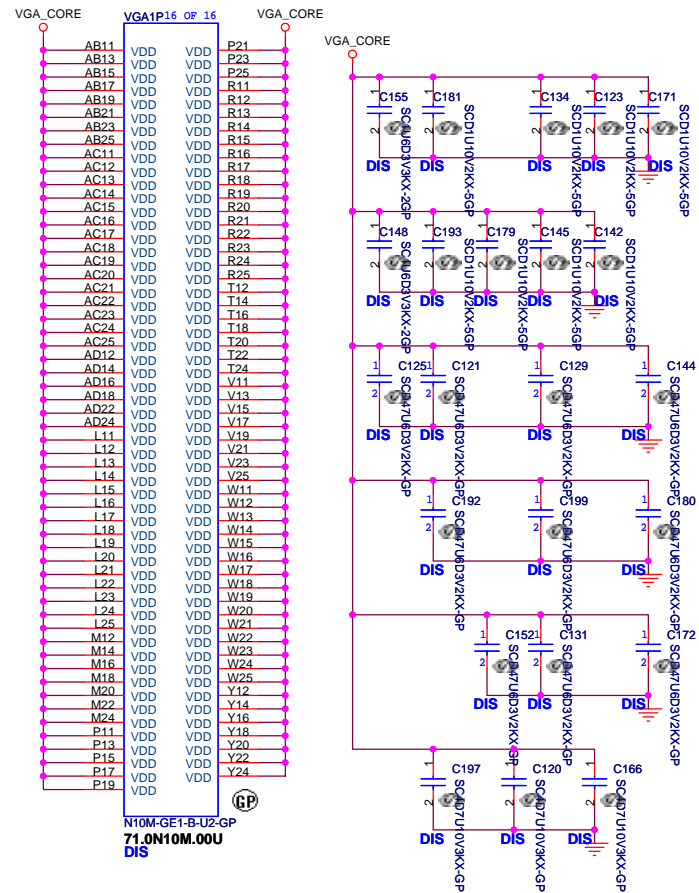
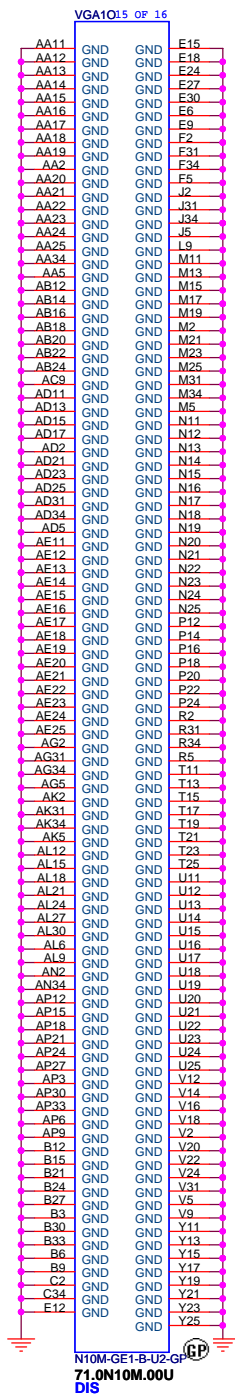


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Title <b>N10M(4/6)</b>	
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Title			
<b>N10M(6/6) POWER</b>			
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SB

12/02

SB

SC

-1

Page3: change C452 C453 from 27P to 33P by vendor's request

Page33: add C872 33P for SIV

Page29: change SPKR\_R1 SPKR\_L1 from 20.F1396.002 to 20.F1214.002 by CE's request

Page18: change LCD1 from 20.F1296.040 to 20.F1230.040 by CE's request

Page24: change USBCN1 from 20.F1290.015 to 20.F1035.015 by CE's request

Page38: change PSCN1 from 20.K0356.006 to 20.K0382.006 by CE's request

Page18: change AMIC1 from 20.F1396.002 to 20.F1214.002 by CE's request

Page3: add R554 and change U24 pin16 from 3D3V\_S0 to 3D3V\_VDD48\_S0

Page3: change C457 C450 C416 C430 C418 from mount to DY and change C456 from DY to mount

Page7: change R192 R195 from 0ohm resistor to 0ohm pad and add R555 RN82 RN83 RN84 RN85 for reflection

Page9: change C275 from UMA to DY and change C349 from mount to DY

Page10: change C243 C758 from mount to DY and change R167 R398 from DIS to DY

Page13: change R216 from 0ohm resistor to 0ohm pad

Page14: change C413 C252 C703 C392 C707 C734 from mount to DY

Page17: change C426 C429 from mount to DY

Page18: change C7 C499 from mount to DY and change R1 from mount to DIS and change R3 from DY to UMA

Page20: add RN86 for DIS HDMI SMBus

Page25: change R45 from 0ohm resistor to 0ohm pad

Page27: change R523 from 0ohm resistor to 0ohm pad

Page7: add R556 pull-low DY for A1 NB

Page28: change AGND & GND and change R509 from 0ohm resistor to 0ohm pad

Page28: change C795 C790 C792 from mount to DY and change R480 R479 from 0ohm to 6K2 and 8K2

Page28: combine C801 C802 two 1u to C801 4.7u

Page28: delete C815 C814 C809 R500 R503 R513 R507 R502 R508 D31 U56 and change U55 to 84.2N702.E31

Page28: change R474 from DY to mount and change R475 from mount to DY for 10dB

Page29: add L29 L30 L31 L32 L33 L34 for ESD

Page31: change R463 R464 R471 R467 R466 R460 R459 R494 R484 R493 R486 R485 R488 R489 R490 R492 R491 R487 from 0ohm resistor to 0ohm pad

Page32: change C487 C477 from mount to DY and change R269 from 0ohm resistor to 0ohm pad

Page12: change C385 C386 from 10p to 7p by vendor's request

Page35: change C136 C169 from 15p to 7p by vendor's request

Page33: change R15 R29 R34 from 0ohm resistor to 0ohm pad and change C542 from mount to DY

Page34: change C42 from mount to DY

Page35: change C615 C626 C638 R395 from mount to DY and change R394 from DY to mount for PCB version

Page36: change DB1 from mount to DY

Page38: add Q35 PWR\_LED7 PWR\_LED8 and change RN4 from 4P2R to 8P4R and change PWR\_LED5 PWR\_LED6 from 83.01221.I70 to 83.00193.A70 for LED type

Page39: change U66 pin1 from CPUCORE\_ON to 1D5V\_PWRGD and change D13 pin1 from S5\_ENABLE to 3V/5V\_EN

Page40: update power sequence logic

Page41: change G43-G50 from open gap to close gap and change R328 R352 R353 R317 R316 R319-R325 from 0ohm resistor to 0ohm pad

Page42: change R532 R545 R552 from 0ohm resistor to 0ohm pad and change G118-G128 G130-G140 from open gap to close gap

Page43: change R246 R233 from 0ohm resistor to 0ohm pad and change G5-G16 G18-G33 from open gap to close gap

Page43: change R246 pin2 from CPUCORE\_ON to 1D5V\_PWRGD and add R500 pull-high 10K 3D3V\_S5

Page45: change G100-G109 from open gap to close gap

Page46: change R157 R187 from 0ohm resistor to 0ohm pad and change G68-G73 G86 G87 G89 G90 G92 G93 G95 G96 G99 from open gap to close gap

Page46: delete TC19 and change TC20 from DY to GFX

Page49: change G55-G67 G74-G77 from open gap to close gap

Page29: change RN75 from 47ohm to 75ohm

Page28: change C804 C807 from 4.7u to 1u 25V X5R

Page45: delete TC24

Page19: delete R104 R129

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Page24: change U47 from 74.00545.A79 to 74.00547.A79

Page20: swap HDMI signals for routing

Page28: change U53 pin22 from AUD\_HP1\_EN to AMP\_MUTE#\_R

Page48: change BAT1 from 20.81094.007 to 20.81156.007

Page22: change ODD1 from 62.10065.541 to 62.10065.751

Page22: change R231 R247 from 0ohm resistor to 0ohm pad

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Page25: change R39 R53 R21 R31 R22 R35 R28 from 0ohm resistor to 0ohm pad

Page46: change L23 from 68.R8210.10V to 68.1R01A.20B and change U43 from 84.04812.A37 to 84.04168.037 by power team's request

Page41: change R344 from 2K87 to 3K16 and change C586 from 0.47u to 0.1u by power team's request

Page41: change U35 U39 from 84.01426.037 to 84.12003.A37 and change U6 U7 U36 U38 from 84.01712.037 to 84.57N03.A37 by power team's request

Page45: change R457 from 11K to 3K48 and change TC23 from 390u to 220u by power team's request

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Page26: change EC7 from DY to mount EMI's request

Page48: change EC28 EC30 EC31 EC32 from DY to mount EMI's request

Page31: change EC51 EC52 EC55 EC57 from 0.1u DY to 22p mount EMI's request

Page5: change C79 C80 from DY to mount EMI's request

Page46: change C659 from DY to GFX EMI's request

Page50: change SPRING\_GND16-SPRING\_GND20 from DY to mount EMI's request

Page50: add EC61-EC67 0.1u by EMI's request

Page20: change R313 R314 from 10K 100K to 18K 47K by NV's request

Page35: change U14 pin83 RN65 pin2 from SHBM to DBC\_EN by annie's request

Page18: change LCD1 pin35 from NC to DBC\_EN by annie's request

Page20: add ER1-ER8 0ohm pad by EMI's request

Page10: change C636 from 1000p DY to 27p mount by RF's request

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Page49: change R406 from 6K2 to 4K75 by power team's request

Page46: change TC16 from mount to GFX

Page50: add TC19 TC24 100u

Page41: change C528 C529 530 C588 C597 C604 from 10u to 4.7u and change C528 C588 from mount to DY

Page46: change C656 C653 from 10u to 4.7u and change C653 from GFX to DY

Page42: change C856 C857 C851 C850 from 10u to 4.7u and change C857 C850 from mount to DY

Page41: change TC5 from DY to mount

Page5: change C553 C538 C552 C539 C547 C536 C548 C537 from DY to mount

Page17: change C426 C428 C429 from 10u to 4.7u and change C429 from DY to mount

Page16: change C440-C442 C463-C465 from 10u to 4.7u and change C440 from DY to mount and change C464 from DY to mount

Page20: change HDMI from 62.10078.161 to 62.10078.171 by CE's request

Page24: change USBCN1 from 20.F1035.015 to 20.F1290.015 by CE's request

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Page46: add C873 33p GFX by RF's request

Page43: add C874 C875 33p by RF's request

Page20: swap U8 pin13 14 47 48

Page33: change R16 from DY to mount

Page47: change R292 from 0ohm resistor to 0ohm pad

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Page33: change MINI2 pin 51 from 5V\_S5\_MIN1 to 5V\_S5\_MIN2

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Page52: change VRAM strap R350

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Title

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